

A New Method of Imaging: Photonic Integrated Interferometric Telescopes (PIITS)

*Multi-Spectral, Low-Mass, High-Resolution
Integrated Photonic Land Imaging Technology*

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Lai

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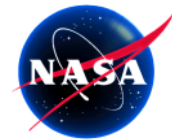
In collaboration with

• Alan Duncan, Samuel T. Thurman, Chad Ogden, Rick Kendrick

Lockheed Martin Advanced Technology Center, Palo Alto, CA, 94304 USA

NASA Grant # NNX16AP60G





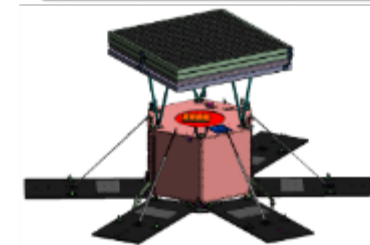
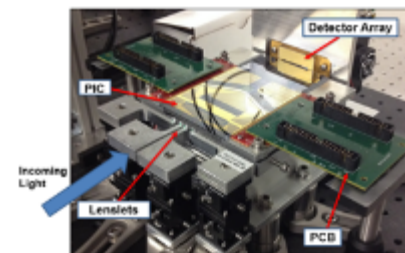
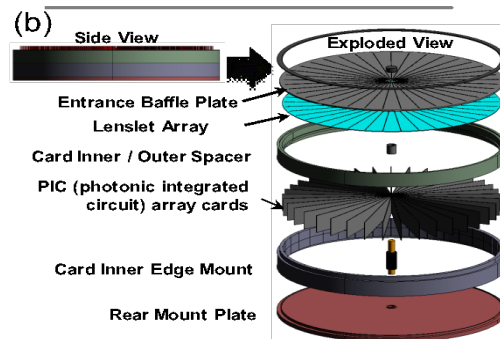
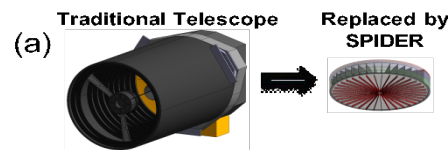
Multi-Spectral, Low-Mass, High-Resolution Integrated Photonic Land Imaging Technology

NASA Grant #NNX16AP60G; PI: S.J. Ben Yoo, UC Davis



Objective

- Design, fabrication and testing of an electro-optical (EO) imaging sensor concept that provides a low mass, low-volume alternative to the traditional bulky optical telescope and focal plane detector array
- Scalability and Feasibility studies for future SLI applications
- Assessment and TRL demonstration of PIC technologies for SLI.



Approach:

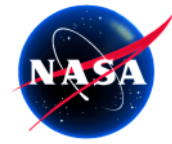
- Conventional approach for imaging interferometers requires complex mechanical delay lines to form the interference fringes resulting in designs that are not traceable to more than a few simultaneous spatial frequency measurements
- SPIDER achieves this traceability by employing micron scale optical waveguides and nanophotonic structures fabricated on a silicon PIC with micron scale packing density to form the necessary interferometers.

Collaborators: Drs. Alan Duncan & Rick Kendrick (Lockheed Martin)

Key Milestones

- M1: Complete an SNR model for SPIDER (1/31/2017)
- M2: Multi-layer PIC design for SPIDER-SLIT complete (5/31/2017)
- M3: 10 channel spectrometer PIC successful operation. (9/30/2017)
- M4: Multi-layer PIC fabrication complete. (11/30/2017)
- M5: Multi-layer PIC achieves fringe generations on > 8 baseline, > 10 spectral bin, 1x5 waveguide input array. (4/30/2018)
- M6: Achieve image reconstruction and simulations. (6/30/2018)
- M7: Multi-layer PIC achieves fringe generations on > 10 baseline, > 10 spectral bin, 2x5 waveguide input array. (1/15/2019)
- M8: Complete scalability and feasibility assessment on SLI missions. (3/31/2019)
- M9: Conduct feasibility and design studies SWIR1 SWIR2 Thermal1 & Thermal2 (4/30/2019)
- M10: Conduct radiation effect experiments and TRL5 (7/30/2019)
- M11: Complete a SPIDER spectrometer conceptual tradeoff (8/31/2019)

Multiple photonic layer: $TRL_{in} = 3 \Rightarrow TRL_{out} = 5$



Motivation

Conventional imaging system's (i.e. telescope) SWaP

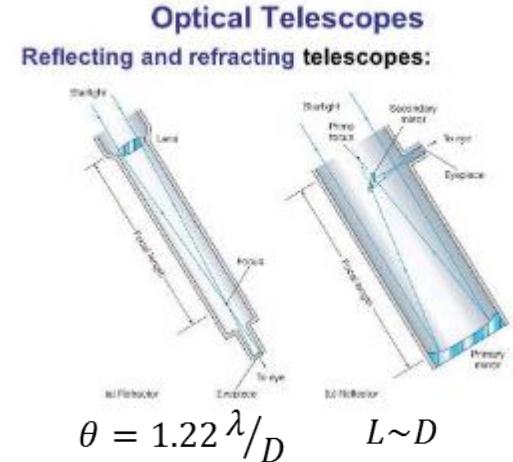
- 1) Aperture Size: ~2.4m in diameter
- 2) Volume: ~ 5m³
- 3) Weight: ~500kg
- 4) Power: ~ 500W



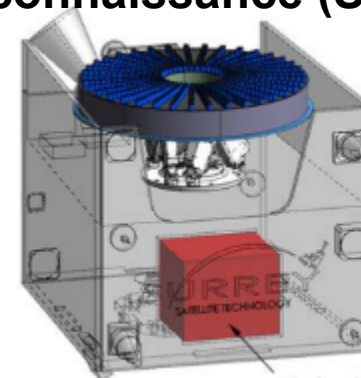
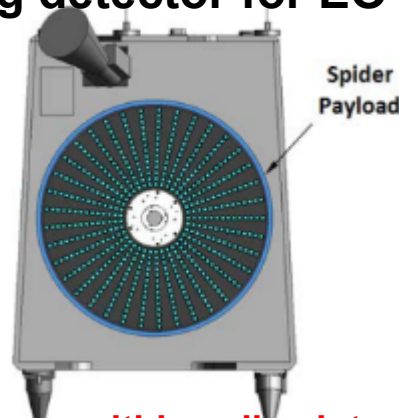
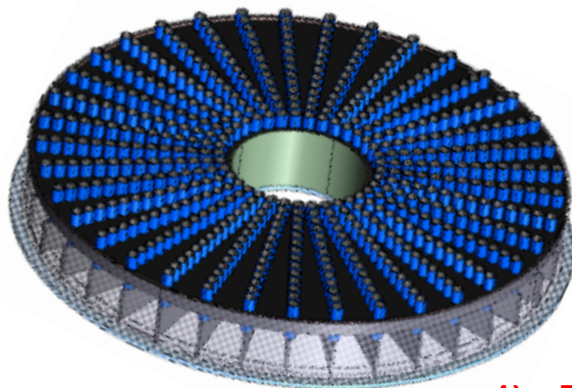
Hubble Telescope



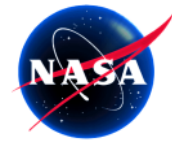
IKONOS satellite



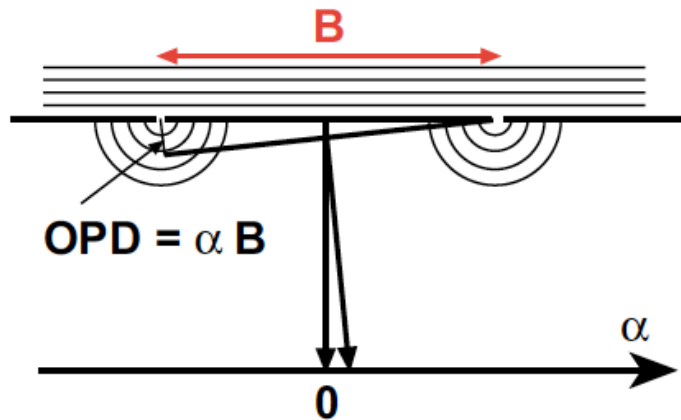
Segmented planar imaging detector for EO reconnaissance (SPIDER)



- 1) Based on multi-baseline interferometric imaging
- 2) Reduce SWaP by the factor of 10~100



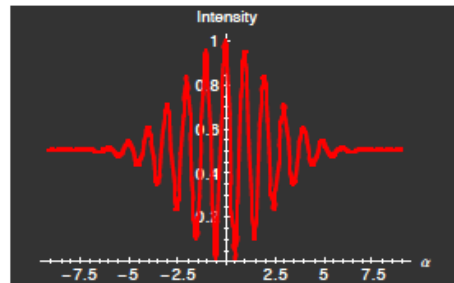
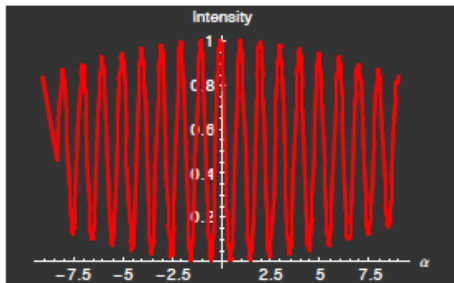
Basic Idea--Young's Two-Slit Experiment



1st Min: $OPD = \lambda/2 \Rightarrow \alpha_{\min} = \lambda/(2B)$

- Light source at infinity at $\alpha = 0$
- Intensity pattern $\sim 1 + \cos$ as a function of α , period length: λ/B
- $OPD >$ coherence length \Rightarrow fringes disappear

Light source at angle α_0
 \Rightarrow fringe pattern shifts accordingly



(First and last picture of a movie)

Figure Courtesy of Andreas Glindemann

 **SPIDER: segmented planar imaging detector for electro-optical reconnaissance**

● Objectives

- Planar “flat panel” telescope with NO large optics
- Large field of view with NO precision gimbals for line of sight steering

● Concept Description

- Light input by large area lenslet array “wired” into interferometer channels using nanophotonics (leverages commercial high density optical interconnect 3D computer chip technology)
- Scalable to larger apertures using fiber coupling of multiple interferometer chips

Linear arrays of lenslets arranged in spoke-like pattern to fill u,v (Fourier) imaging plane

Interferometer Tube Assy Array
14 per row
37 rows

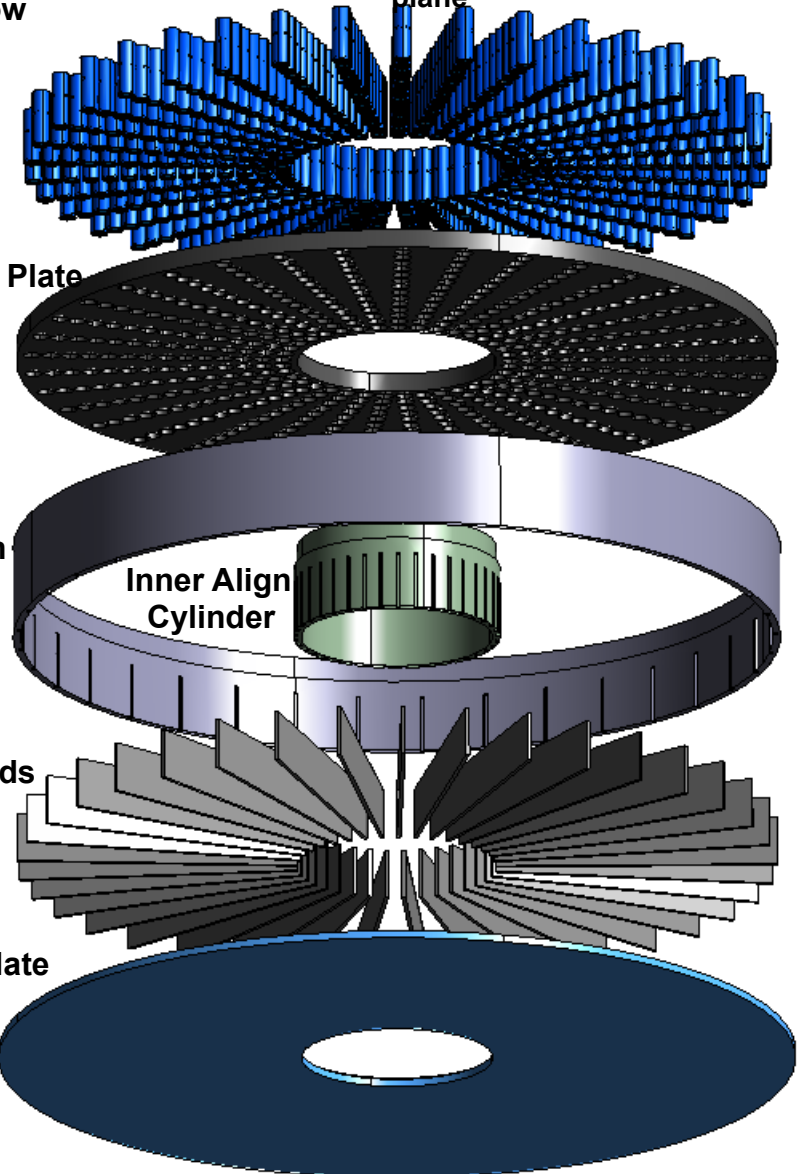
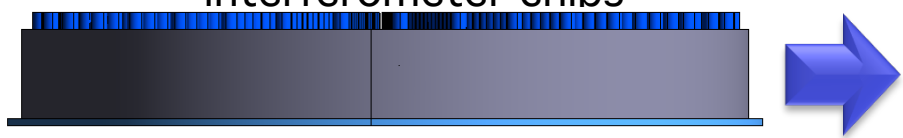
Array Plate

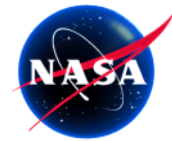
Outer Align Cylinder

Inner Align Cylinder

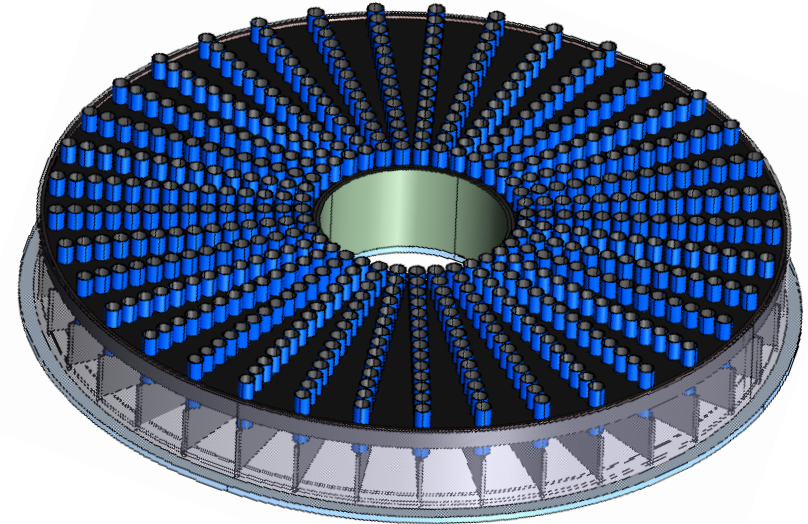
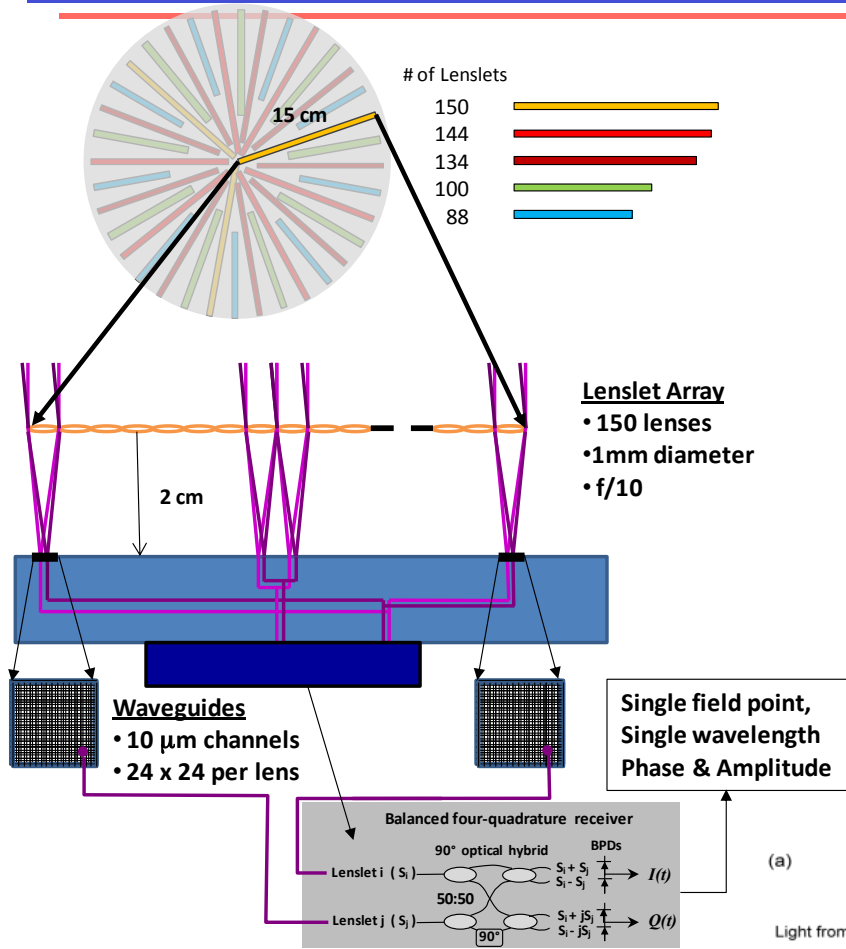
Silicon Cards (37)

Back Plate

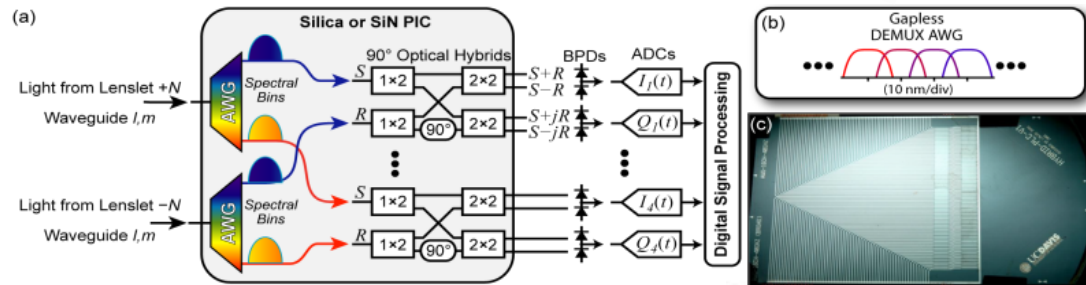


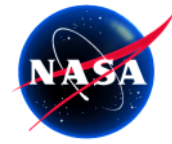


SPIDER PIIT Approach



Spectrally Resolved High Resolution Interferometric Telescope



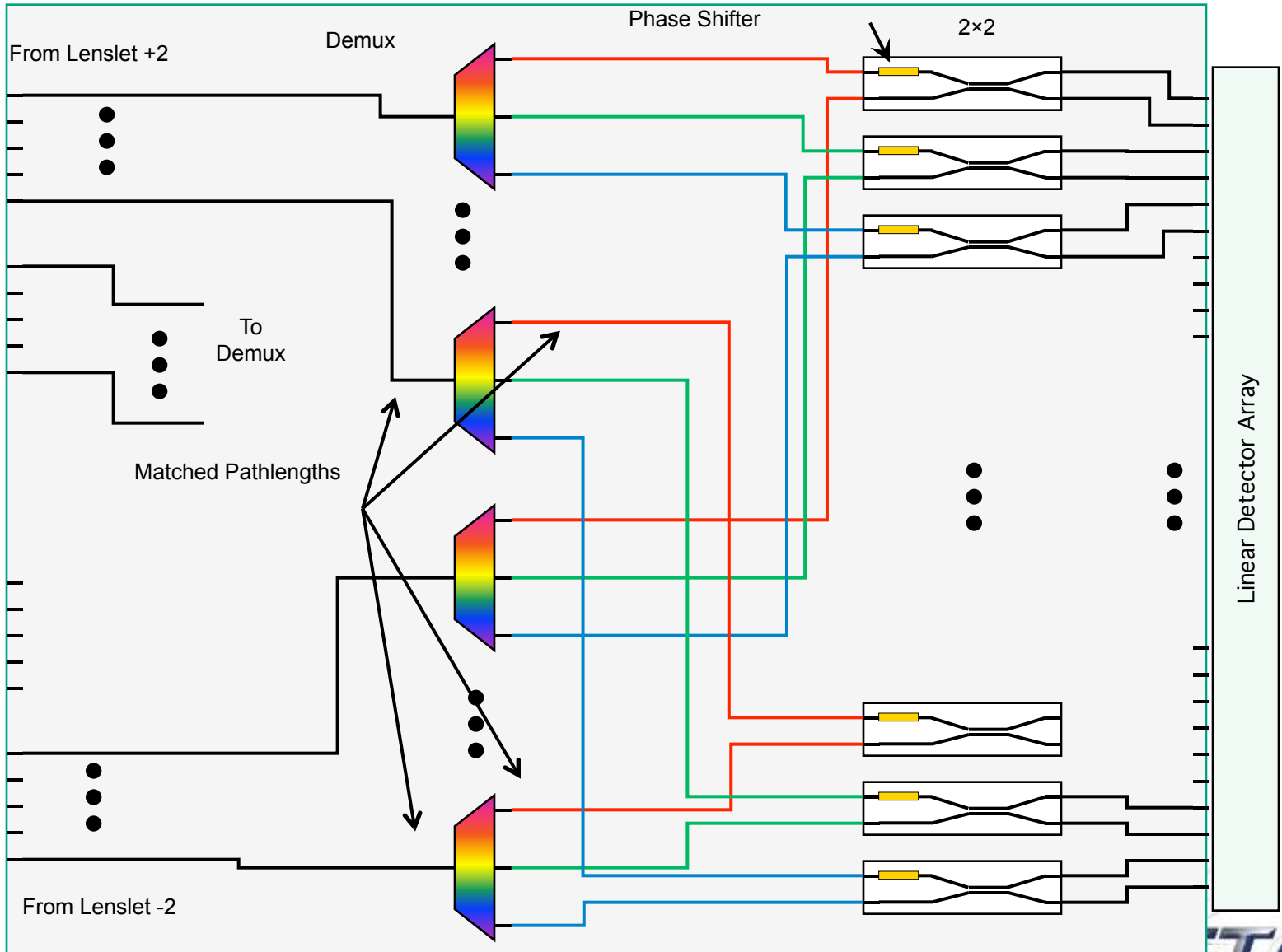
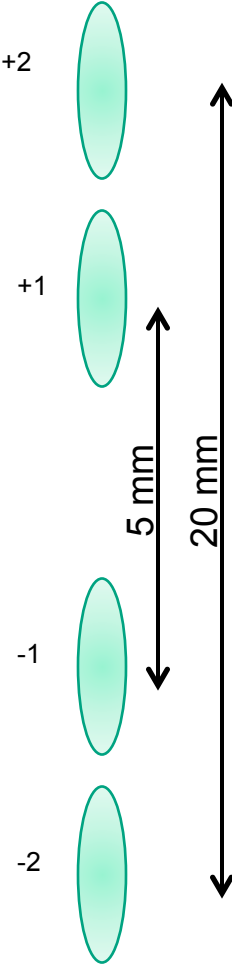


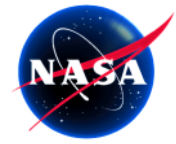
Our Previous SPIDER Photonic Integrated Circuits (NIAC I & II)

10-Spatial-Channel \times 3 Spectral Band SPIDER PIC Single Layer

60 Outputs

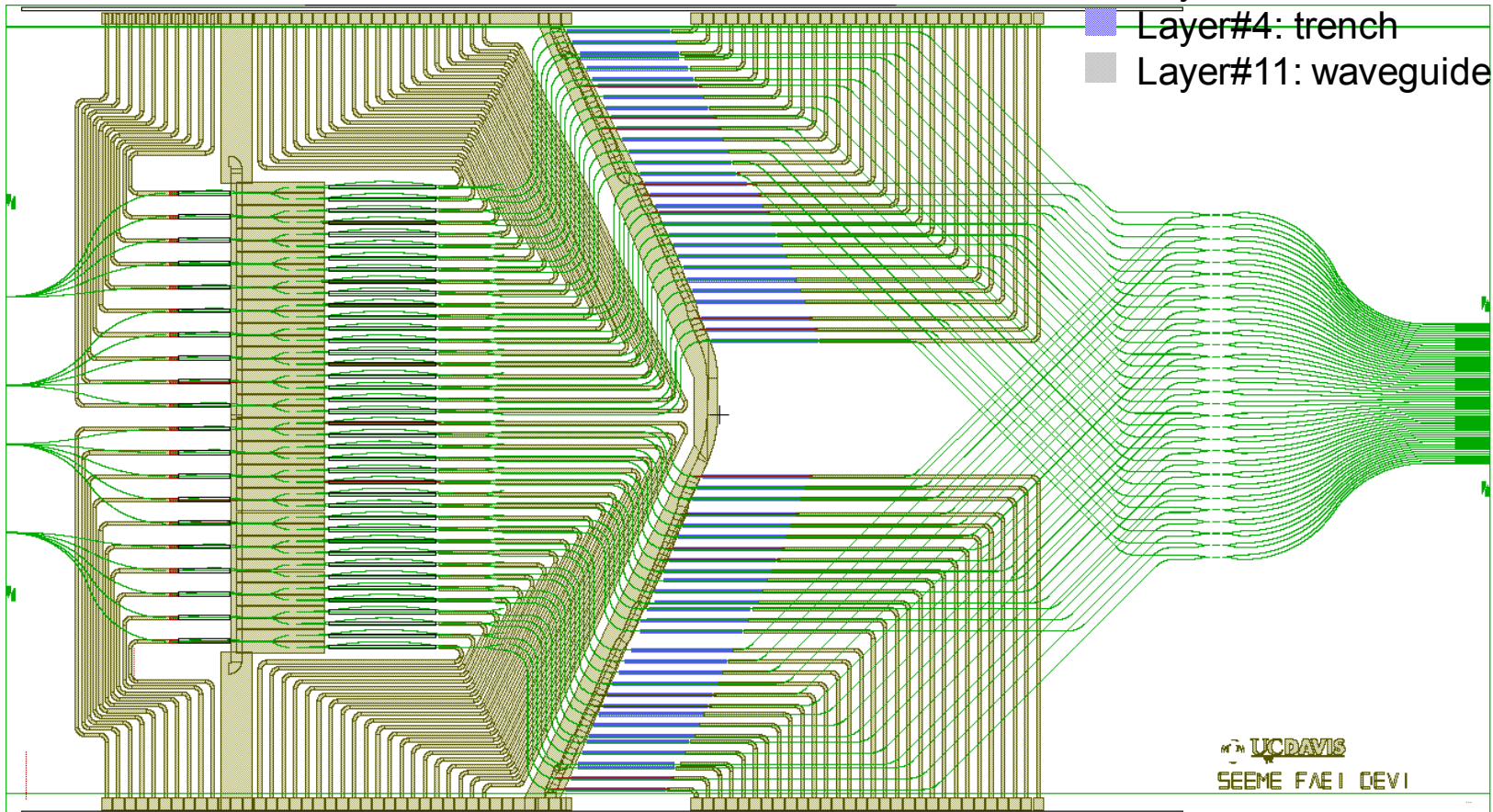
5 Waveguide
Inputs for
Each Lenslet



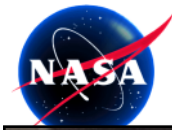


10-Spatial-Ch x3 Spectral Band SPIDER PIC Layout

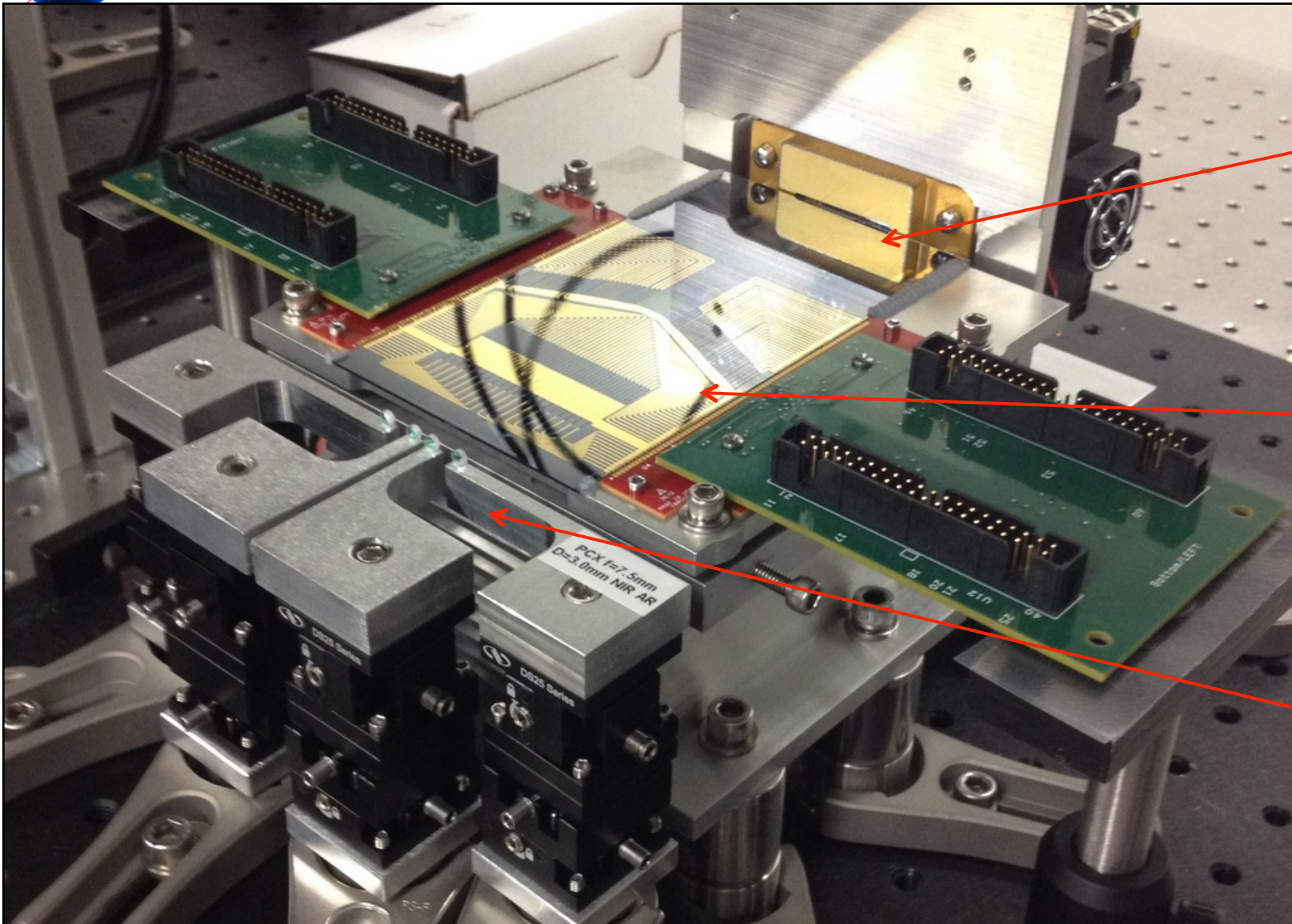
- Layer#1: waveguide
- Layer#2: heater
- Layer#3: electrode
- Layer#4: trench
- Layer#11: waveguide keep o



NASA NIAC and DARPA funded work



Packaged PIIT-SPIDER PIC



Linear Detector Array

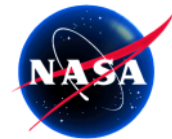
PIC

Lenslets

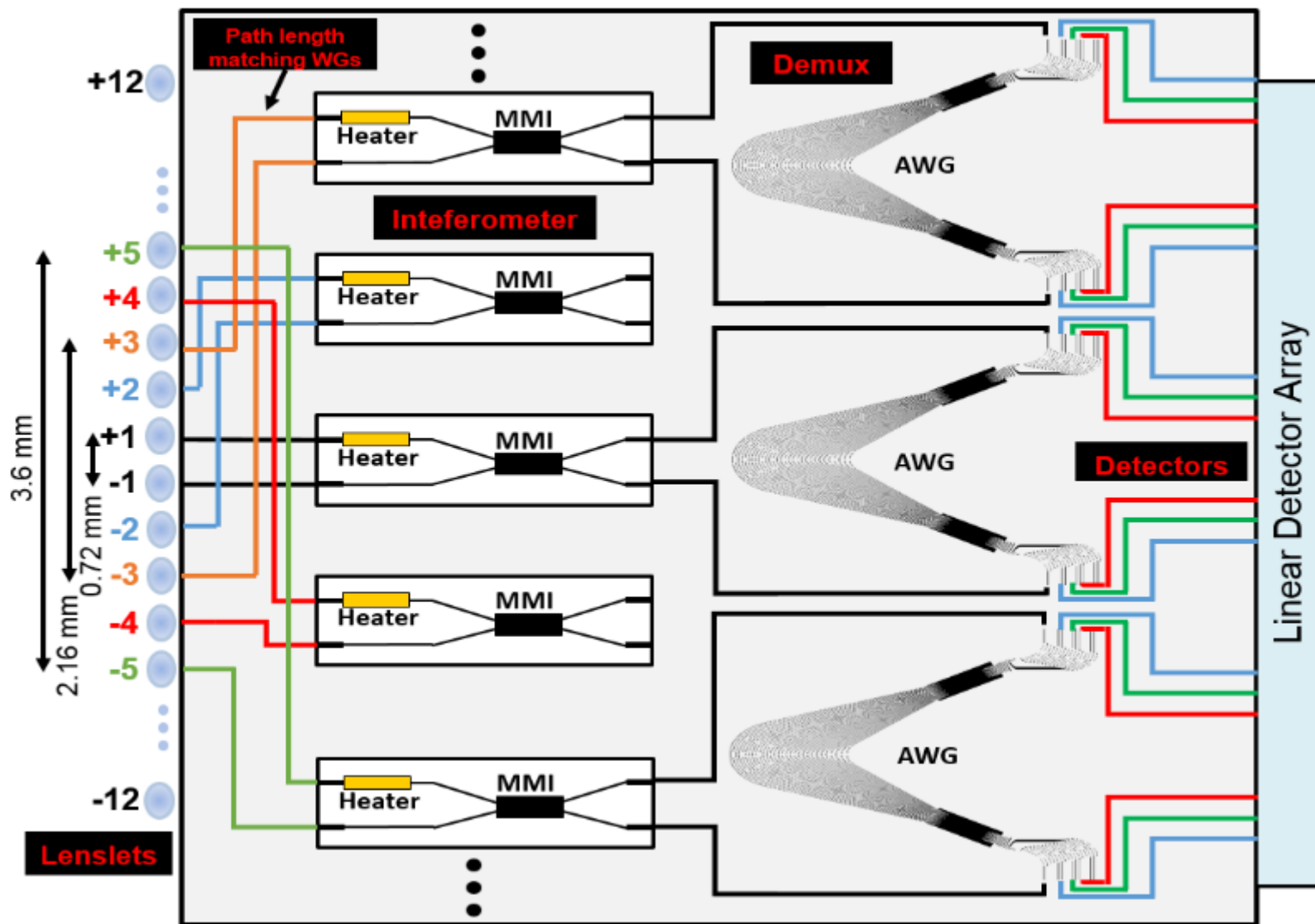
NASA NIAC and DARPA funded work

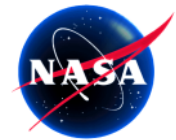
PIIT: Photonic Interferomic Integrated Telescope





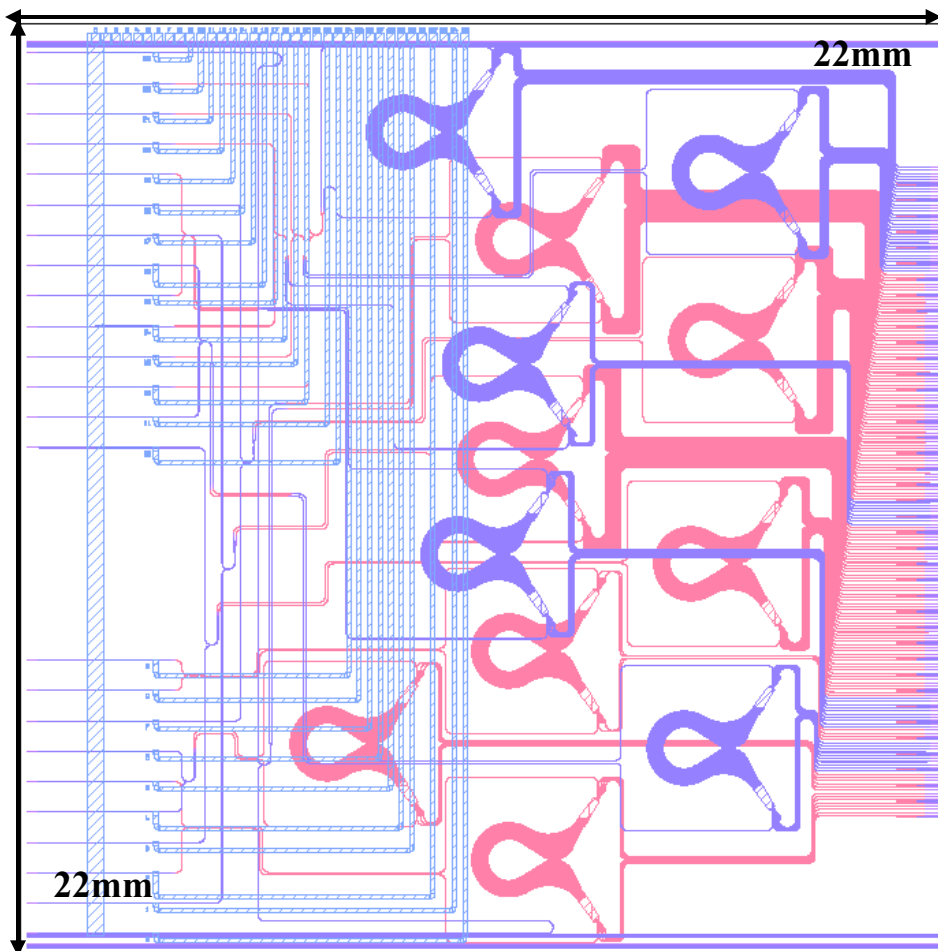
Our New SPIDER Photonic Integrated Circuit Design





Our New Photonic Integrated Circuit Draft Plan (NASA SLIT)

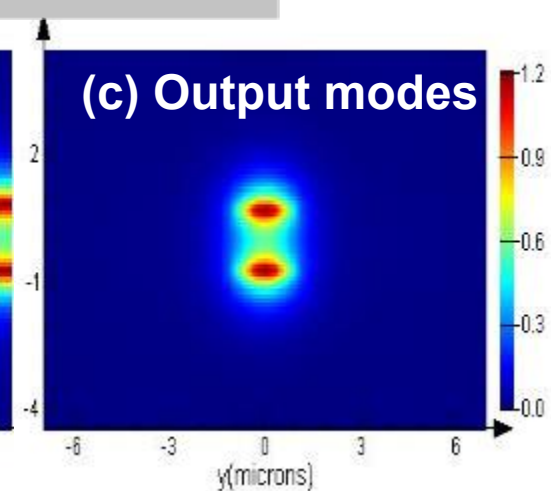
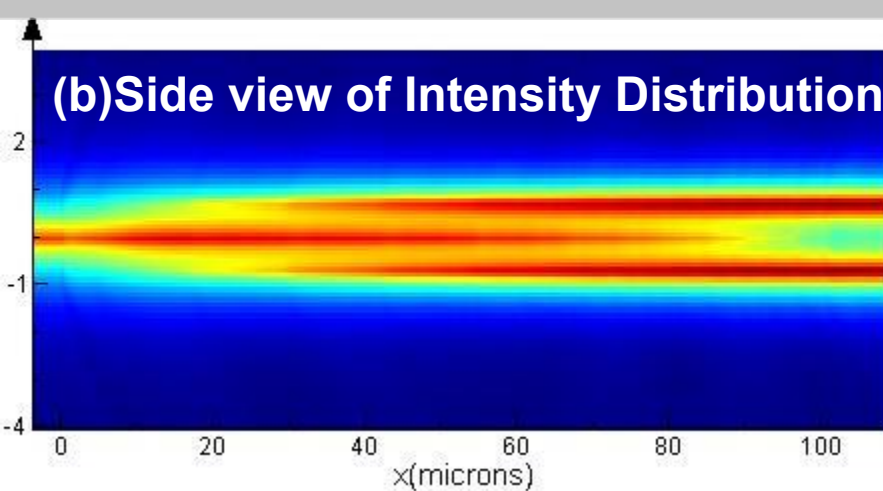
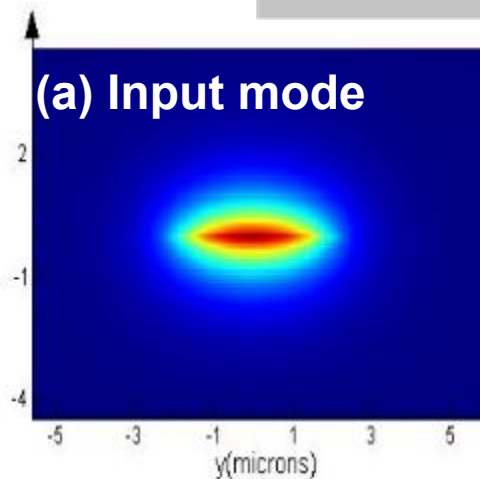
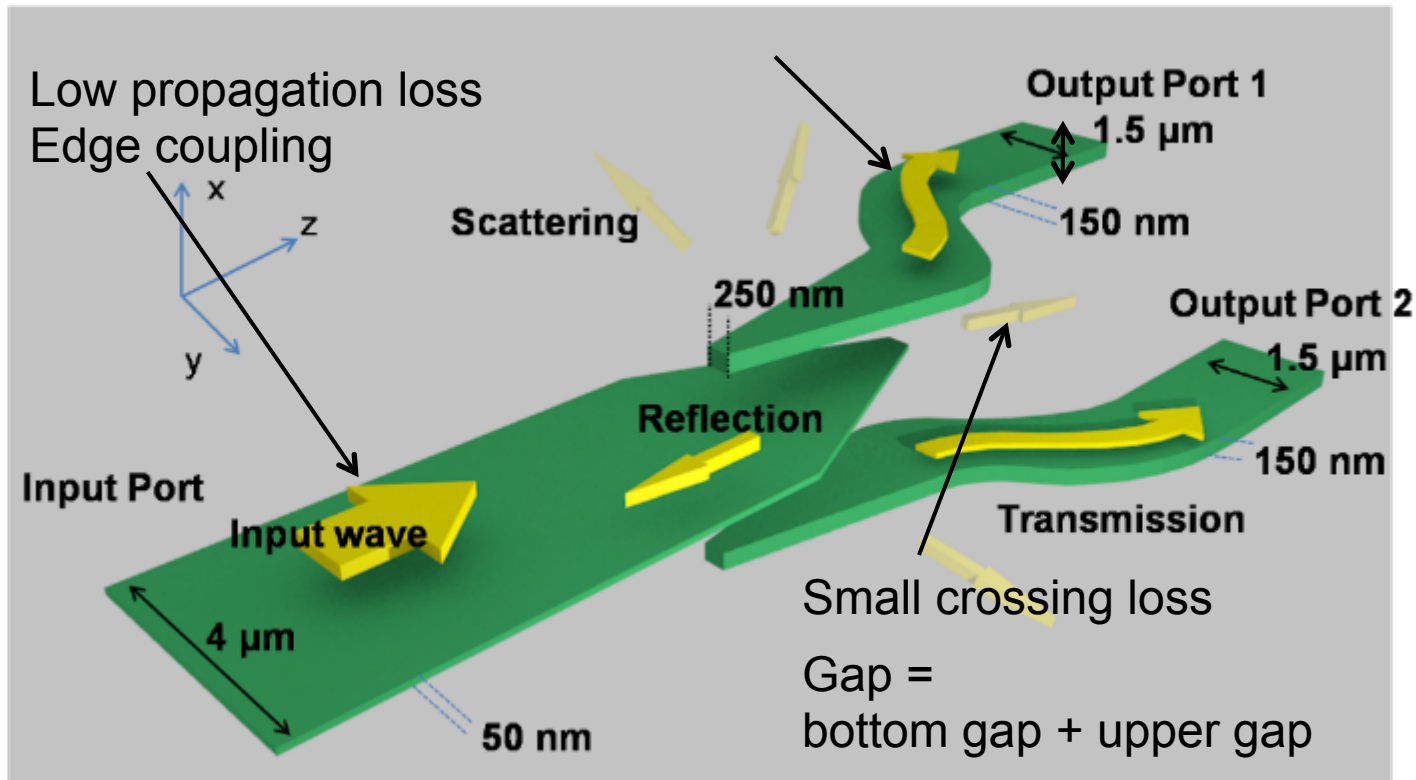
Si_3N_4 PIC

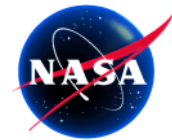


• What's New:

- Si_3N_4 instead of SiO_2 : nearly 10x reduced dimension or 100x reduced footprint area
- Three Layers instead of One: More compact footprint with lower crosstalk
- Projection Lithography instead of Contact Litho: higher yield, higher resolution ($0.18 \mu\text{m}$ instead of $1 \mu\text{m}$)
- Silicon CMOS compatible manufacturing platform instead of silica PLC: more ubiquitous foundry availability; possibility of integration of CMOS and detectors.

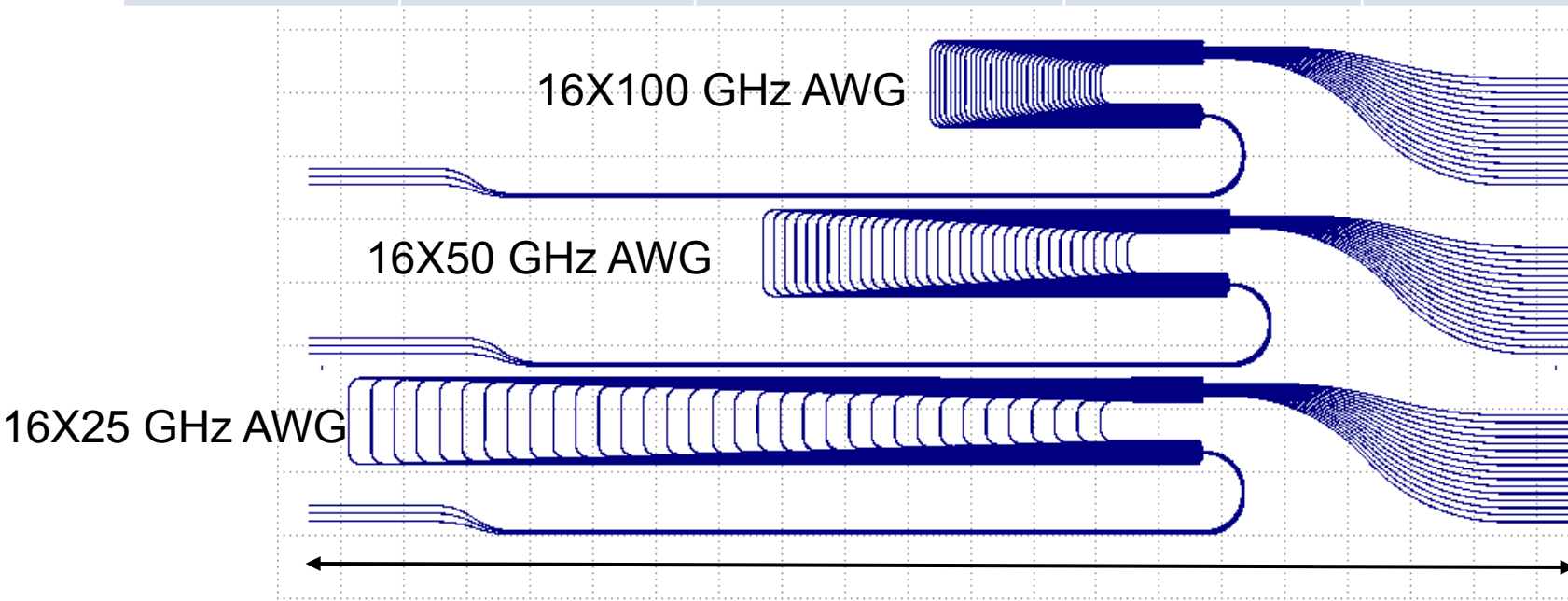
 **Multilayer 150nm/50nm/150nm Si₃N₄ PIC Platform for the new SPIDER PIIT Design**

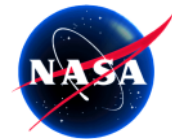




SiN Arrayed Waveguide Gratings - Design

No. Channel	Channel Spacing (GHz)	No. Waveguide	FSR (THz)	Foot Print (mm ²)
16	100	34	1.8	2.2X0.7
16	50	34	0.9	3.7X0.7
16	25	34	0.45	6.8X0.7





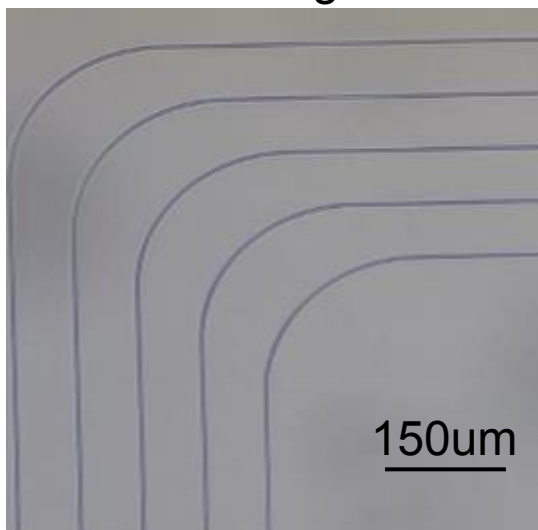
SiN Arrayed Waveguide Gratings – Fabricated Device Photo

16 channel X 50 GHz AWG

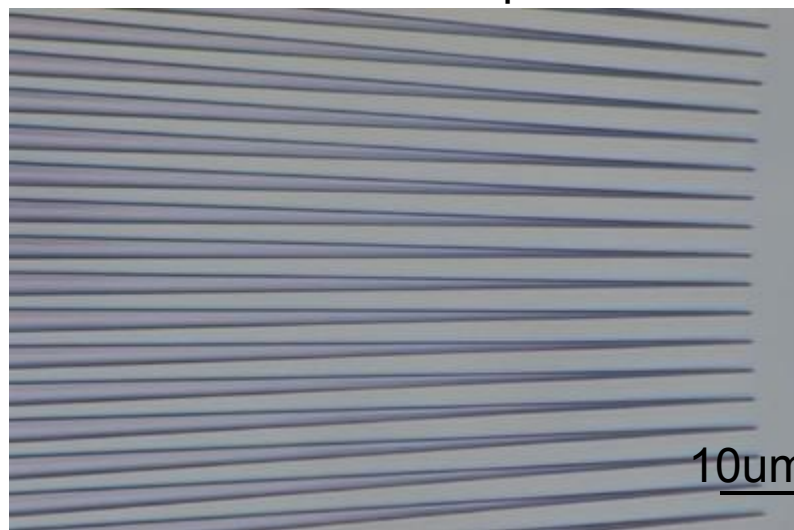
6.787 mm



Bending



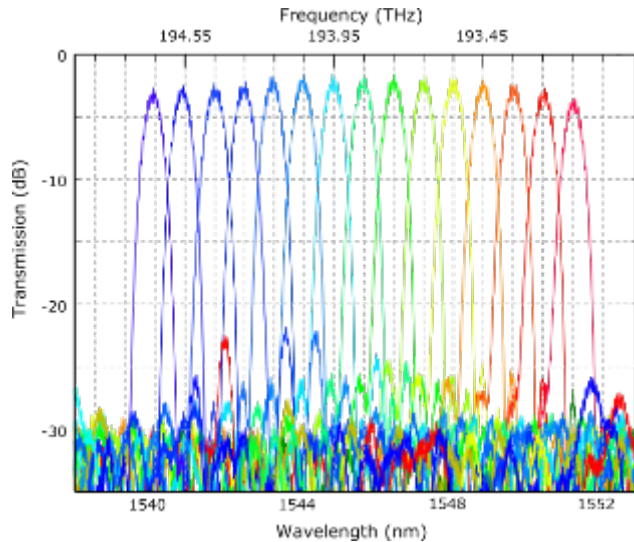
Star Coupler





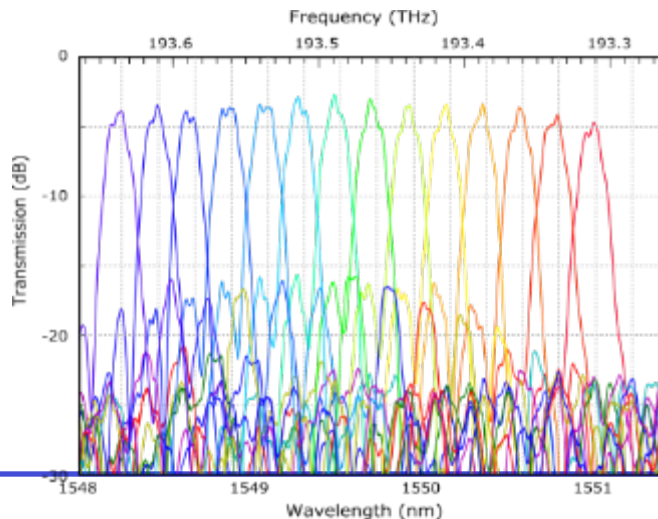
Arrayed Waveguide Gratings – Fabricated Device Transmitted Spectrum Measurements

16 ch X100 GHz AWG



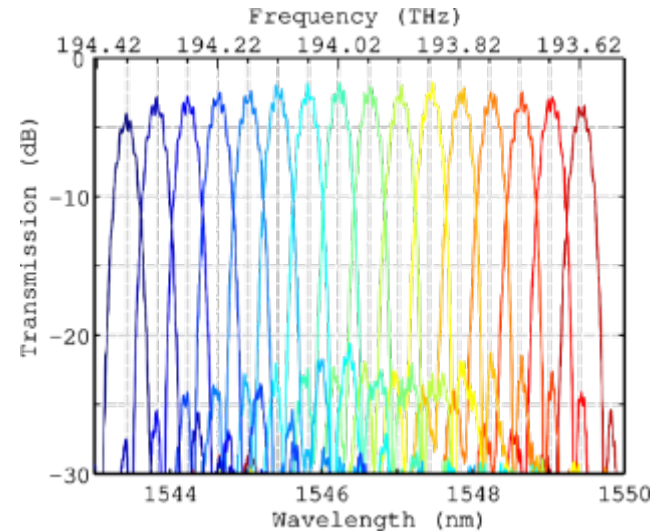
Insertion loss: 1.7 dB
Crosstalk: -21 dB

16 ch X25 GHz AWG

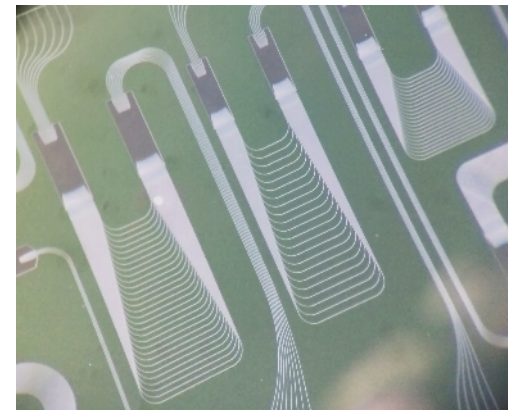


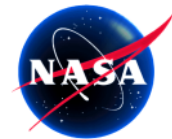
Insertion loss: 2.7 dB
Crosstalk: -13 dB

16 ch X50 GHz AWG



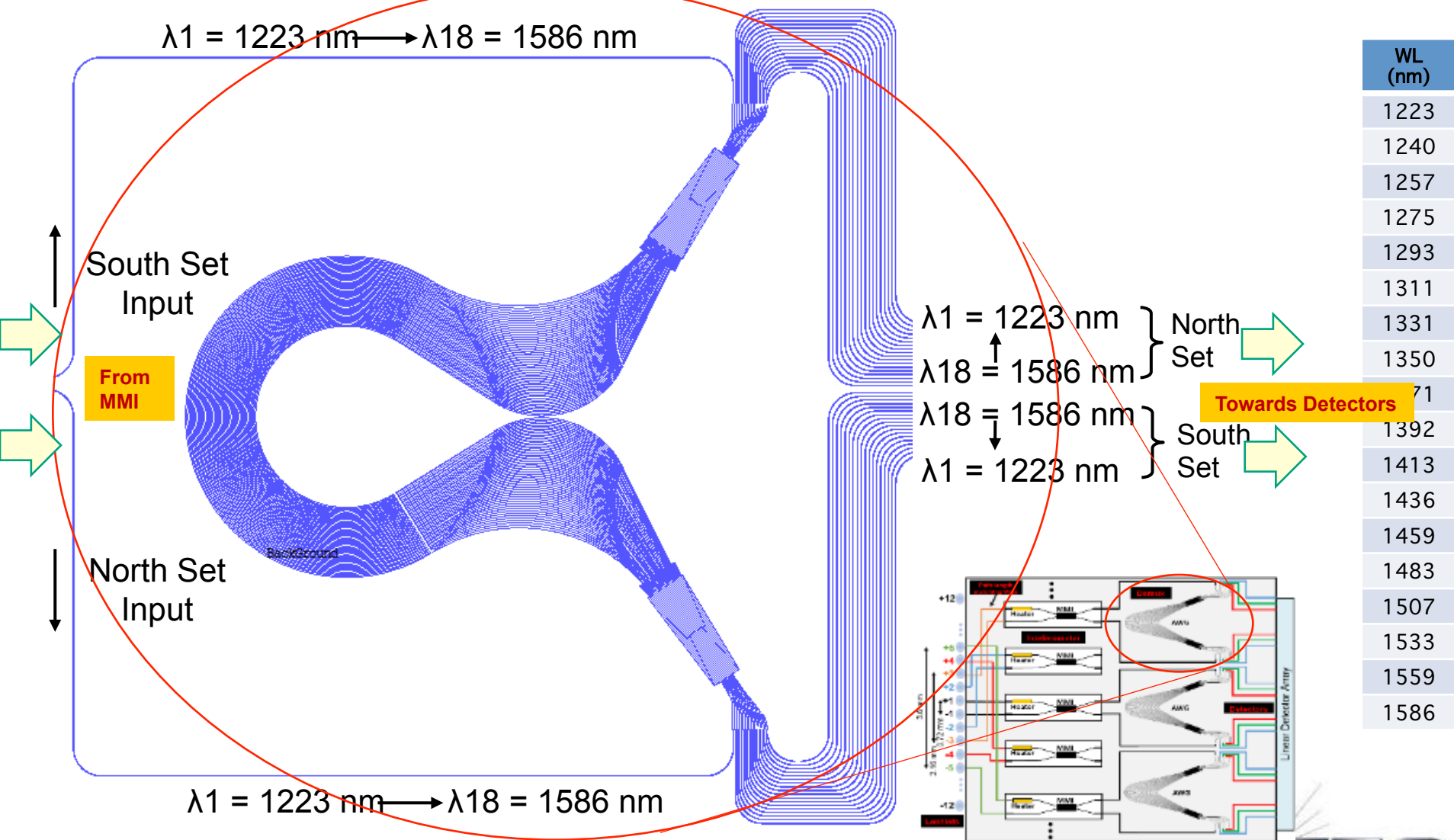
Insertion loss: 1.8 dB
Crosstalk: -20 dB

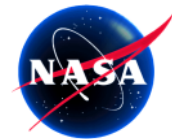




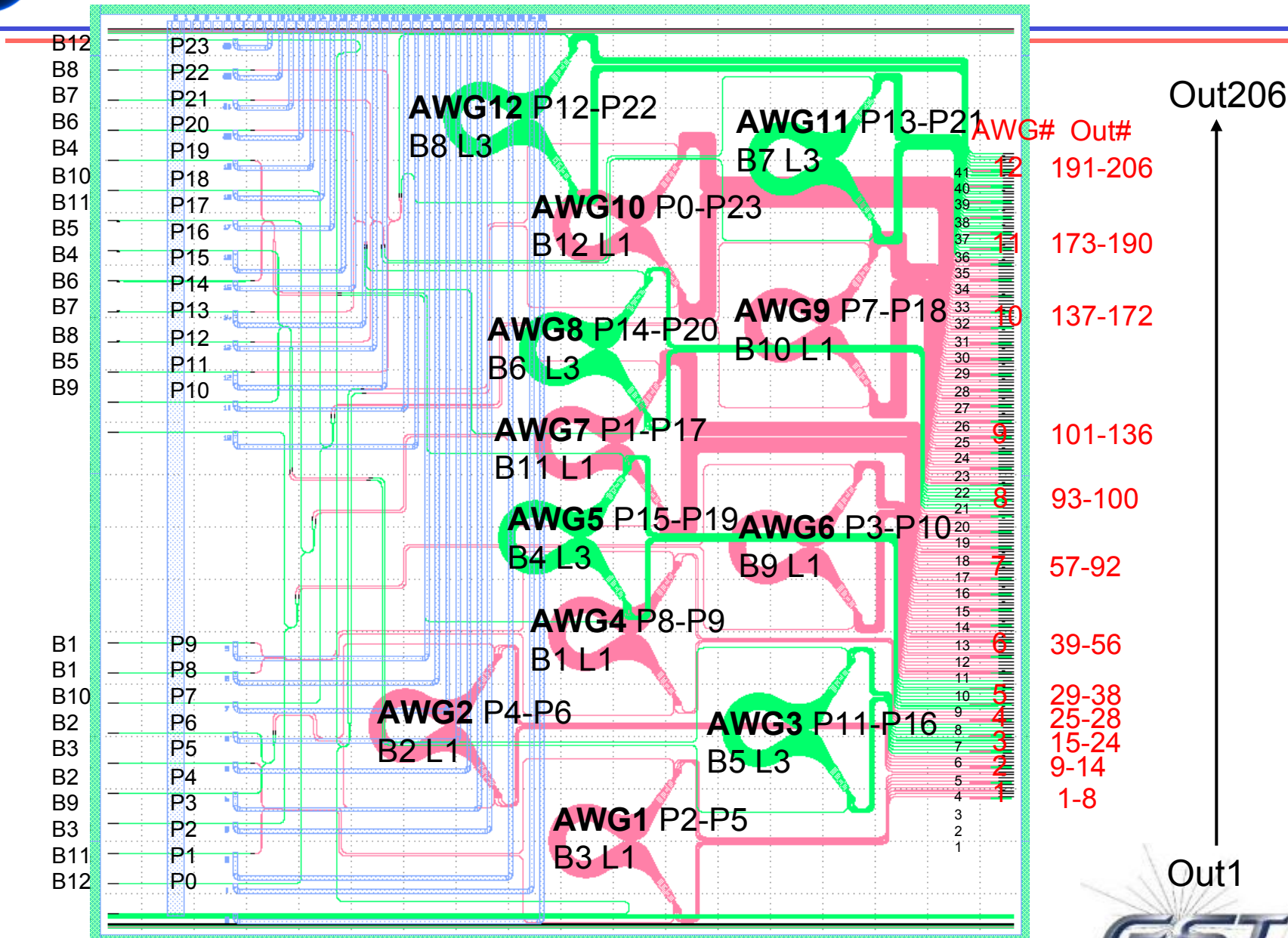
Spectrometer Design for the new SPIDER: 18 Ch (3.3THz) Arrayed Waveguide Gratings

Symmetric Dual Arm Design for Interfacing with Mach-Zehnder Interferometer





Our New SPIDER PIC Design and Layout





Scene Generation and Imaging Experiments

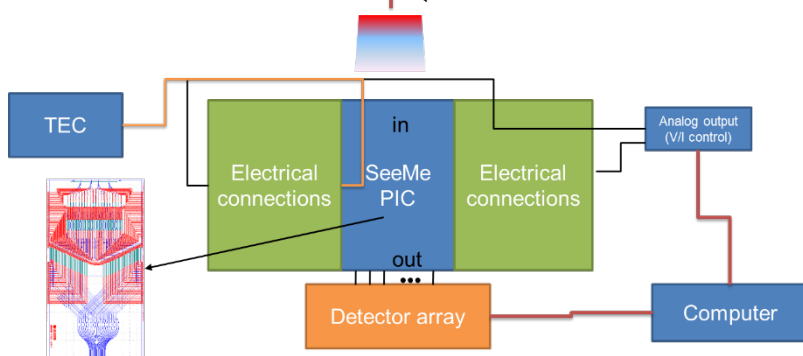
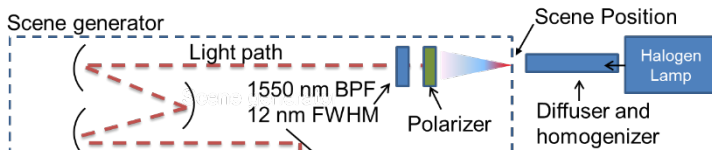
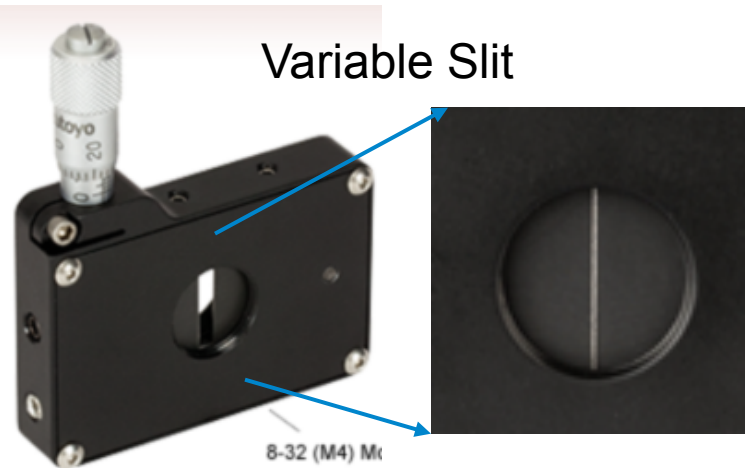
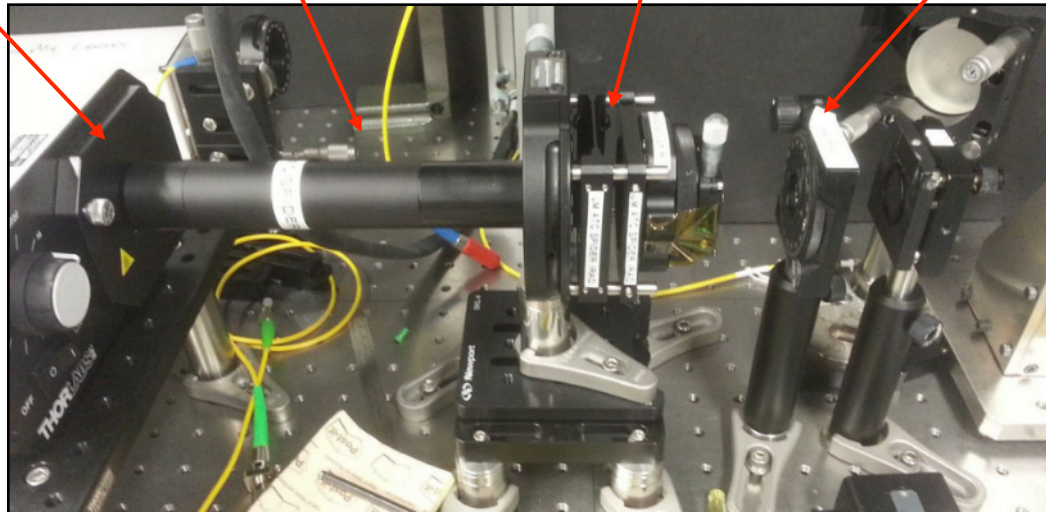


Halogen Lamp Source

Source Homogenizer

Scene Location

Polarizer



Ronchi rulings

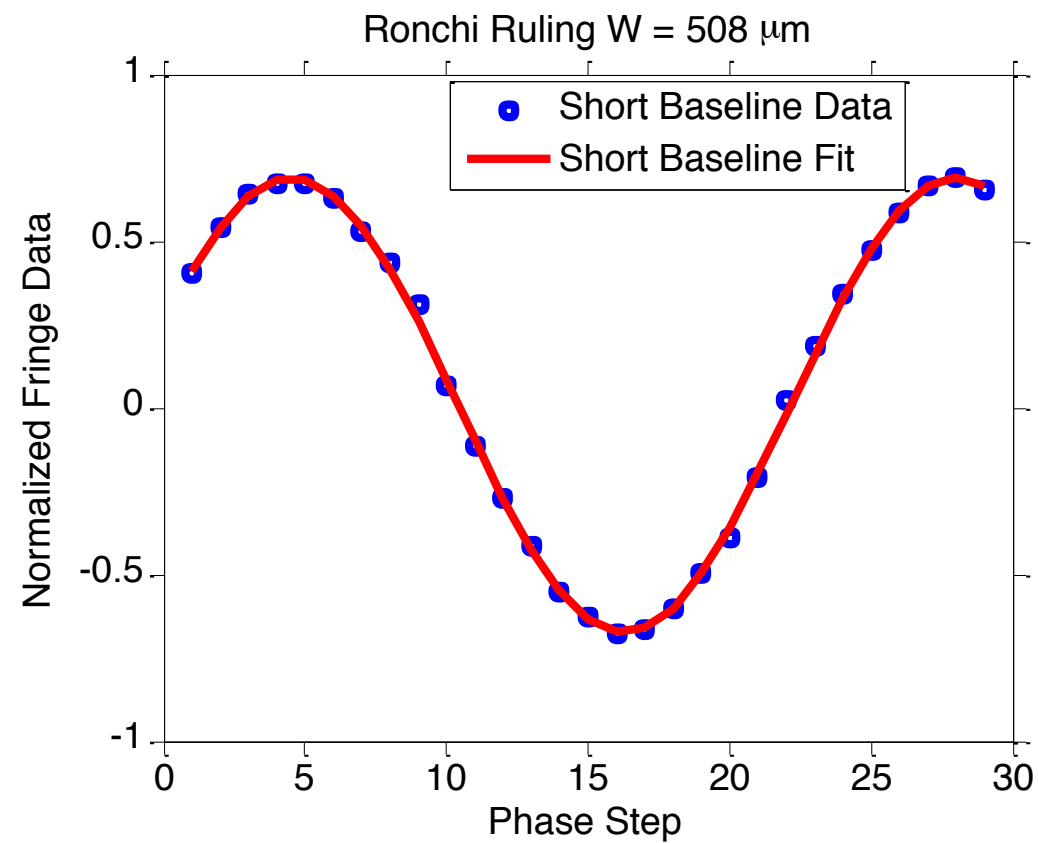




Ronchi Ruling – 5 mm Baseline



Ronchi Ruling illuminated by the lamp with 12 nm filter and polarizer



After a sinusoidal fit:

- The amplitude is 0.75
- The RMSE of the fit is 0.017
- Estimated signal to noise ratio for a single data point is 44
- Estimated SNR of the amplitude would be $44 \times \sqrt{29/4} = 118$
- The visibility should be close to 50% for this case

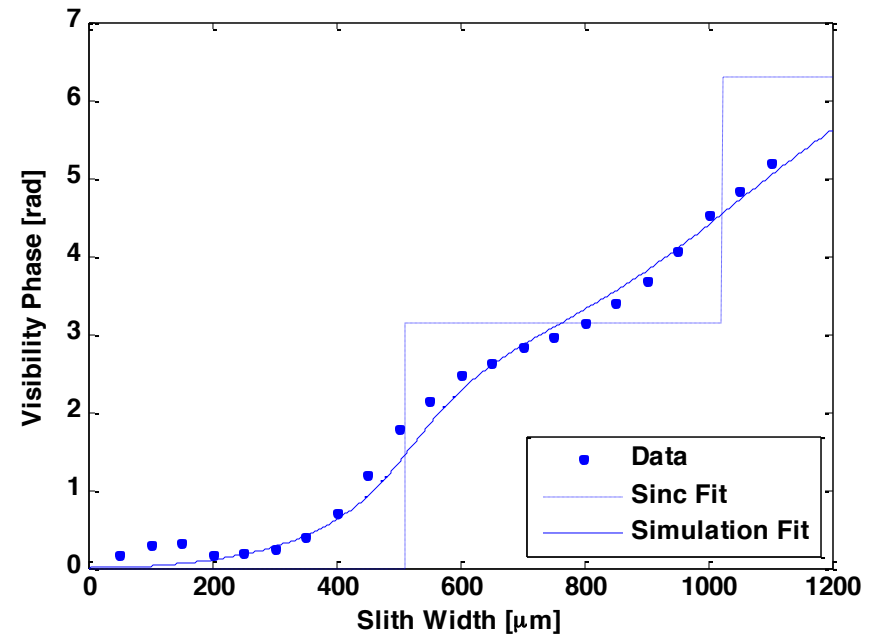
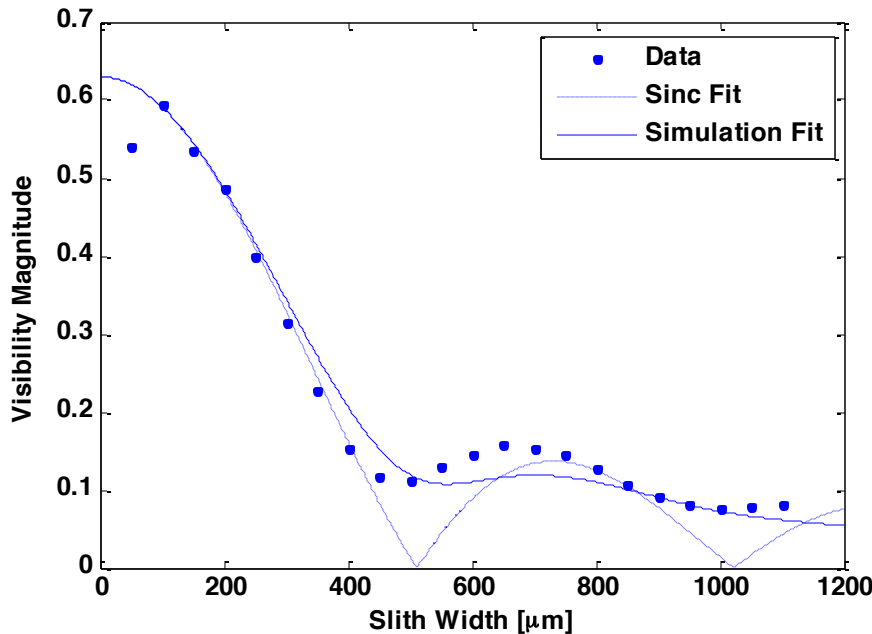
This indicates that it is possible to measure visibilities down to ~0.5% for this scene (if we could adjust the baselines) before we get to the SNR = 1 noise floor



5 mm Baseline Measurement and Curve Fit



- **Curve Fit shows Offset = 300 μm** (Suspect there is an additional offset between the individual lenslet FOV's)
- **In the future, measure photometric signal levels for individual lenslets to obtain direct information about offset**



- **Curve fit quality is good**
 - **Offset between slit and FOV = 250 mm**
 - **Adjusted constant + linear phase terms of visibility data**

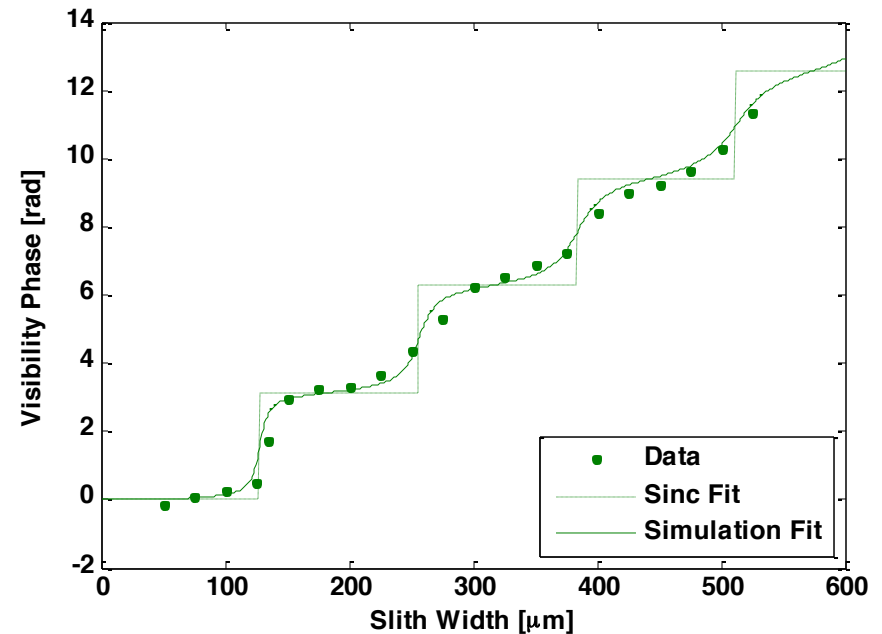
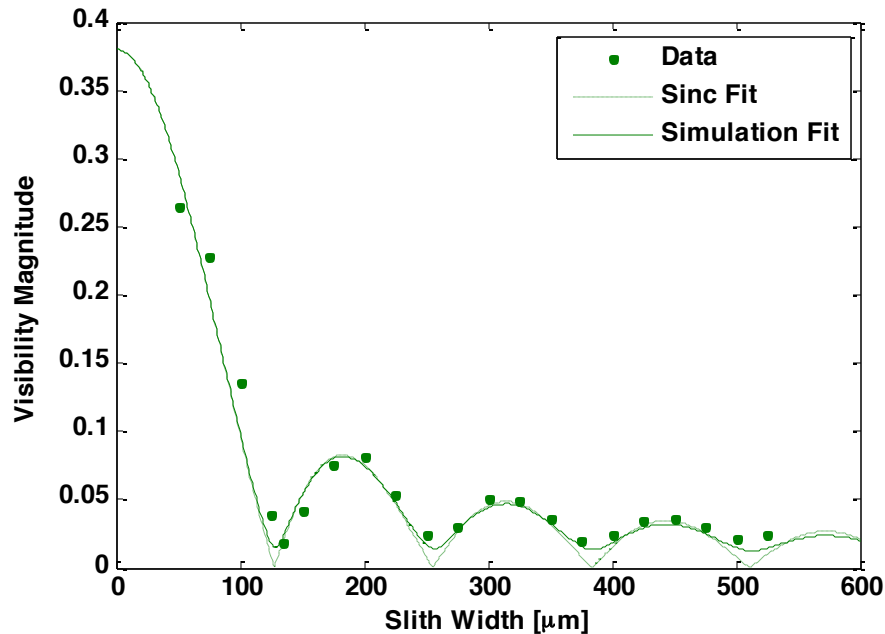
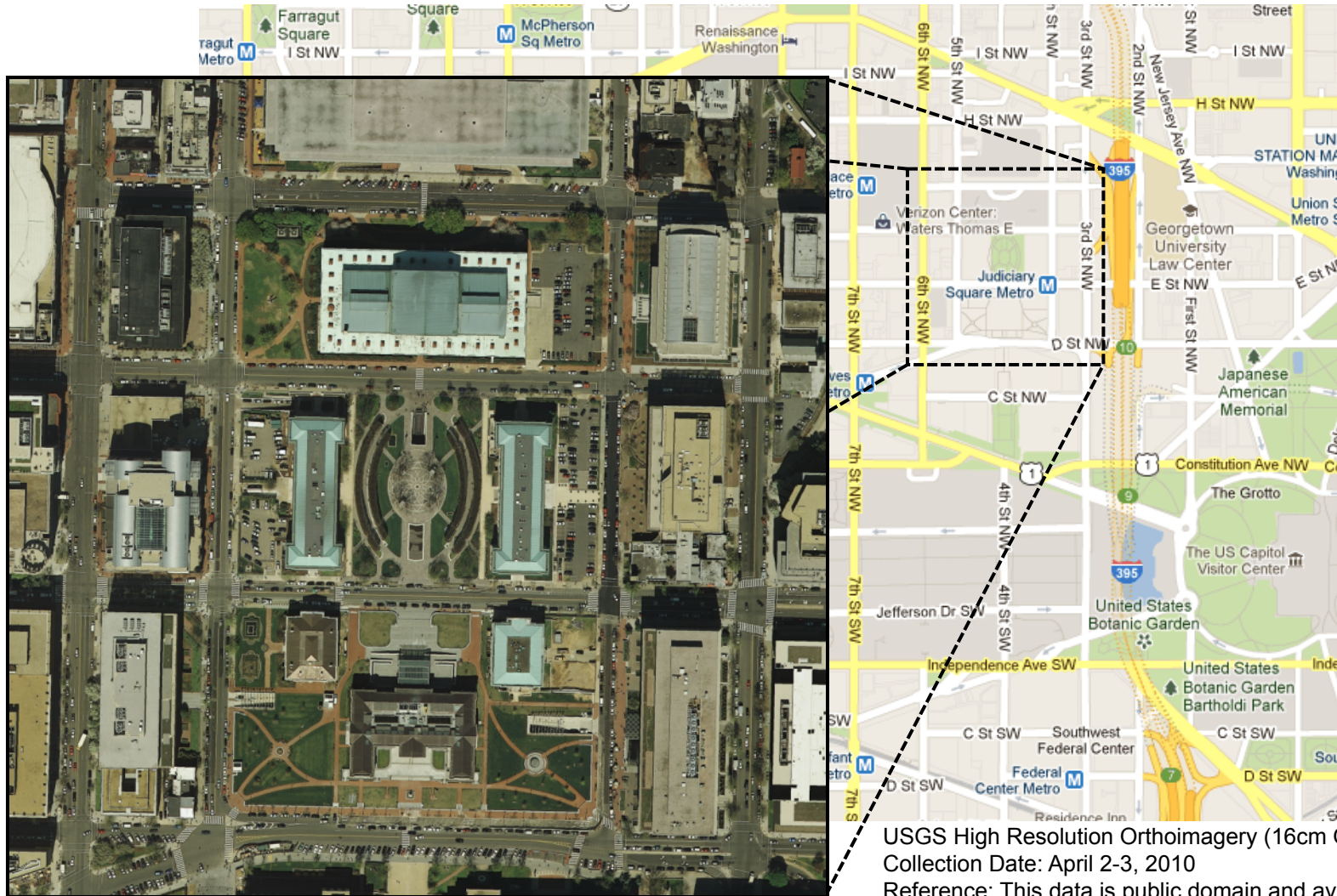




Image Reconstruction Simulations: Scene Data used for Imager Simulations



Judiciary Square, Washington, D.C.



USGS High Resolution Orthoimagery (16cm GSD)
 Collection Date: April 2-3, 2010
 Reference: This data is public domain and available from
 the United States Geological Survey through <http://nationalmap.gov>.

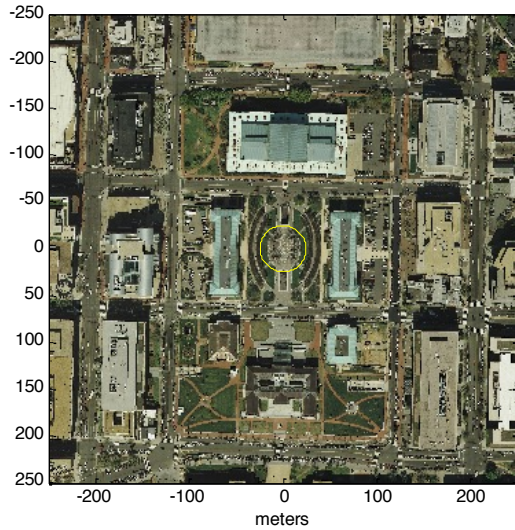
Lockheed Martin IRAD work



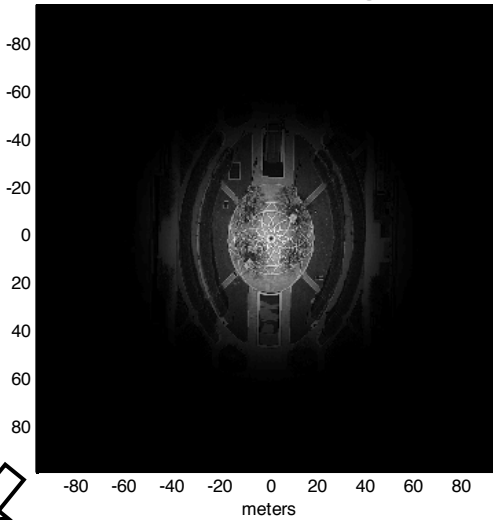
Simulation for a Single Sub-Image



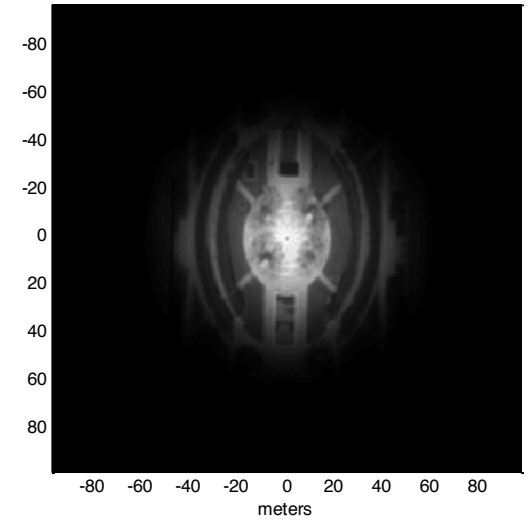
1. User selects FOV for sub-image



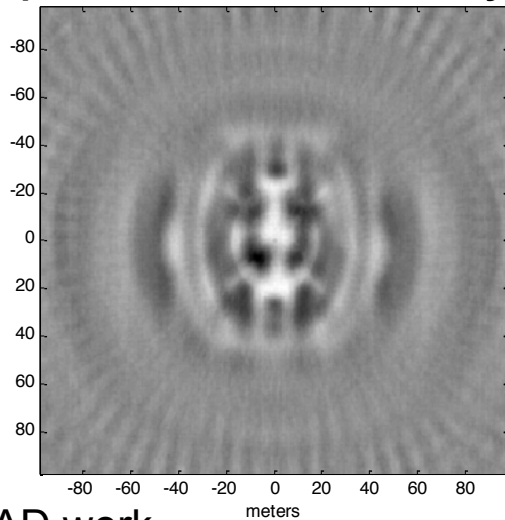
2. Crop scene and apodize (fiber coupling)



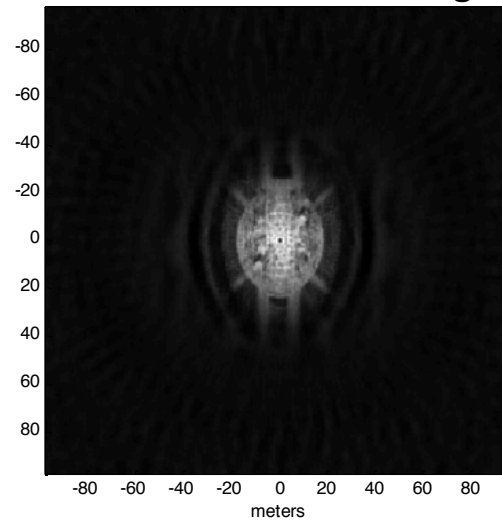
3. Make a conventional comparison sub-image



4. Compute $u-v$ data & make "dirty" image

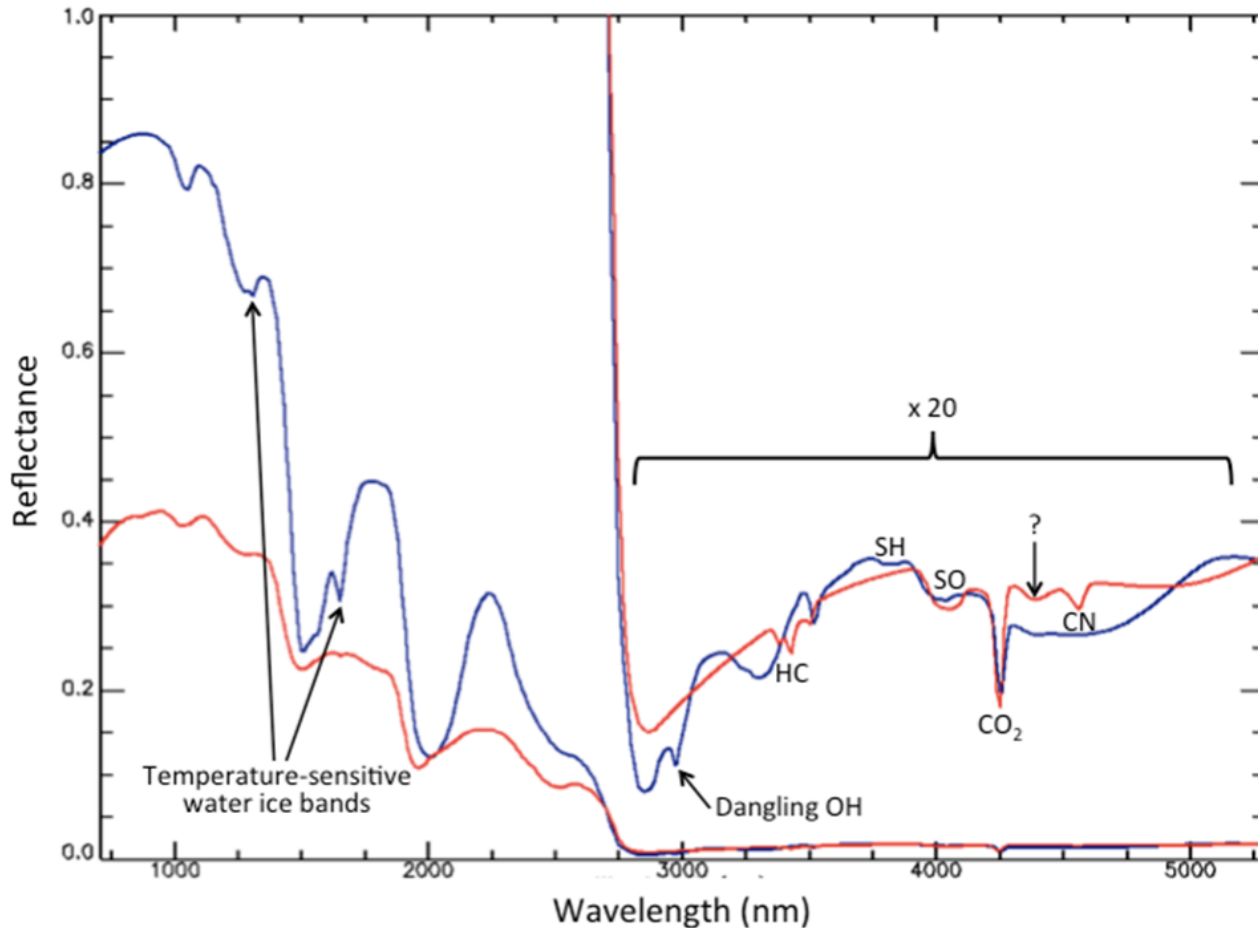


5. Reconstruct sub-image



Lockheed IRAD work

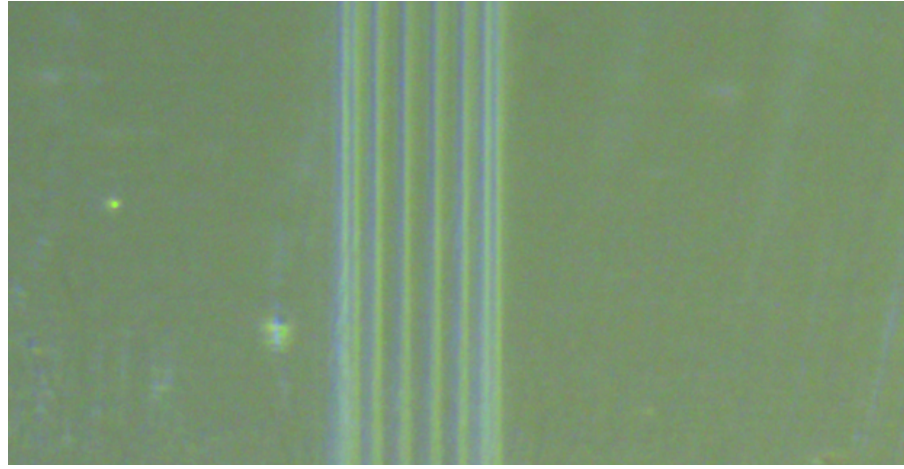
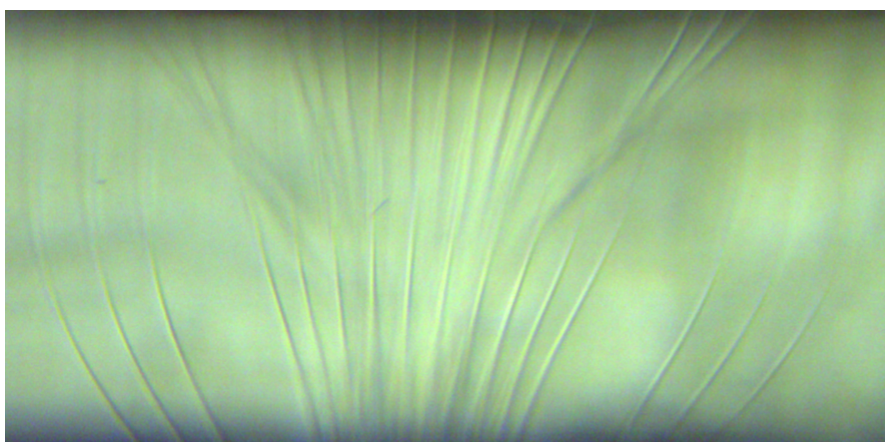
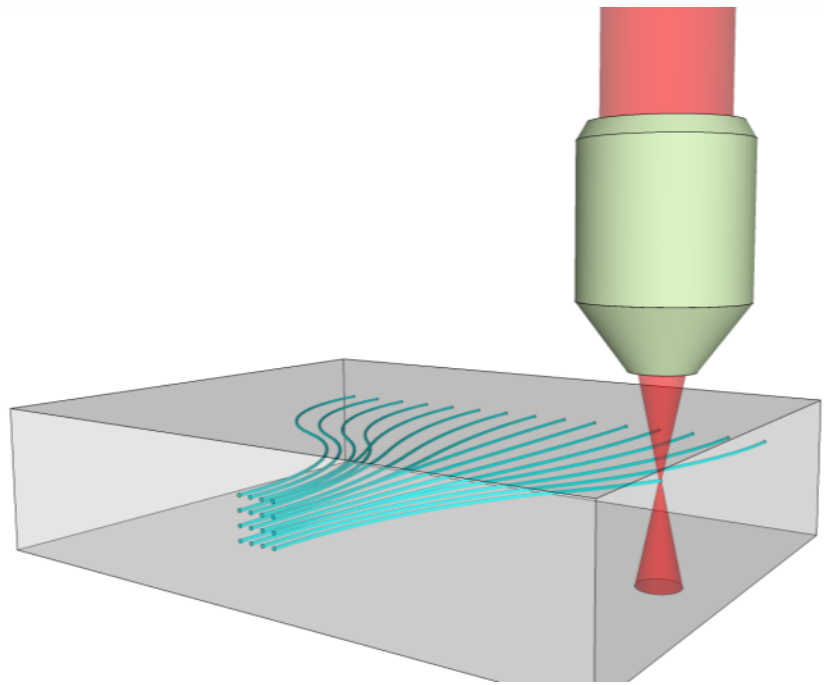
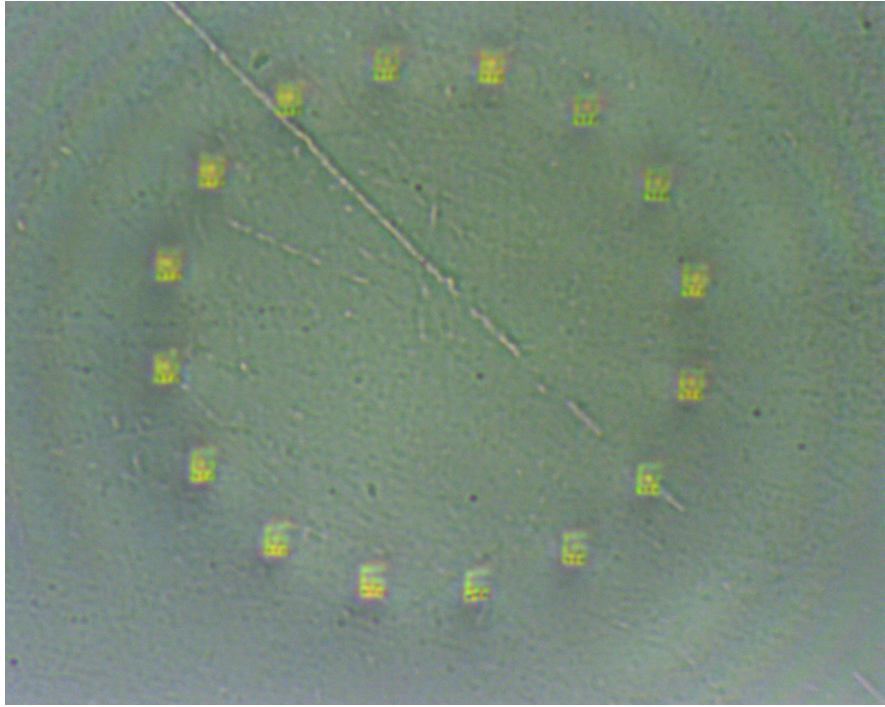
“Notional reflectance spectra for ice-rich regions (blue curves) and ice-poor regions (red curves) on Europa ... in the 1–5 μm spectral range.”



Europa Study 2012 Report – Europa Multiple Flyby Mission, JPL D-71990 (2012)



3D Integrated Photonics by Ultrafast Laser Inscription





3D Waveguide Writing at UC Davis



~150 mm/s writing speed

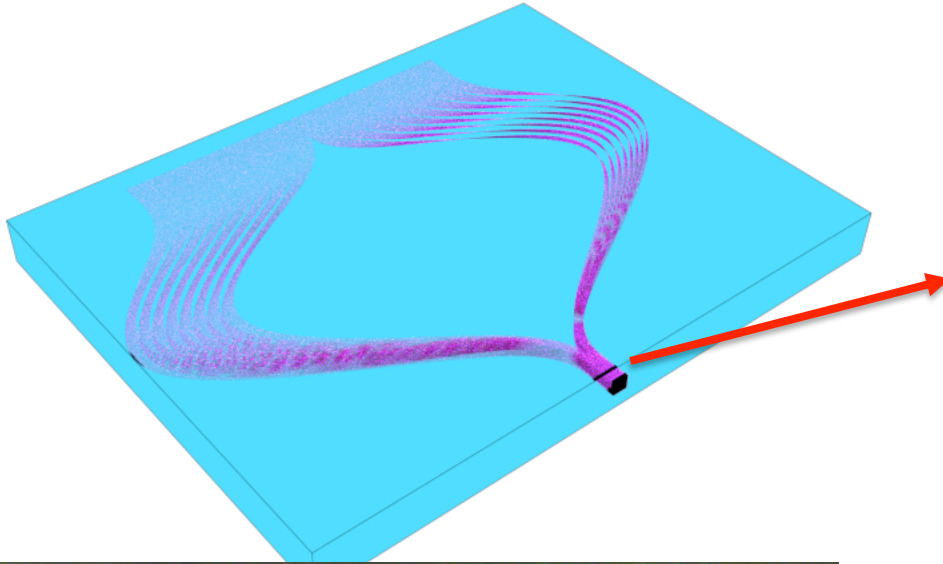


Precision and Low Loss 3D waveguide Fabrication by fs Laser Inscription

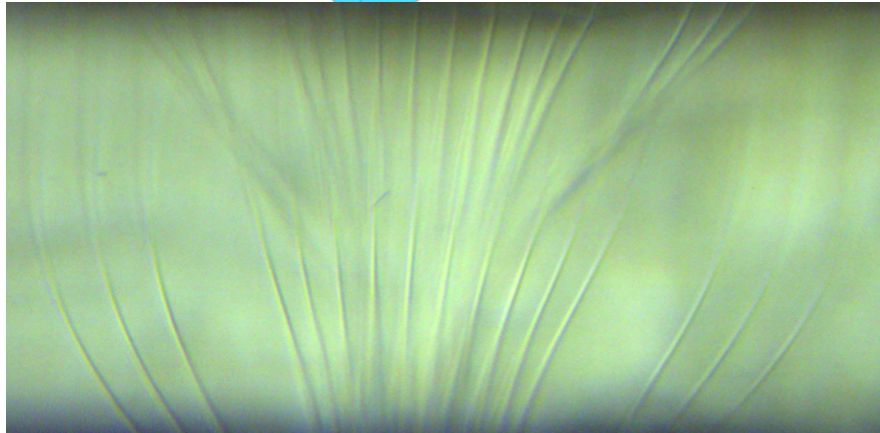
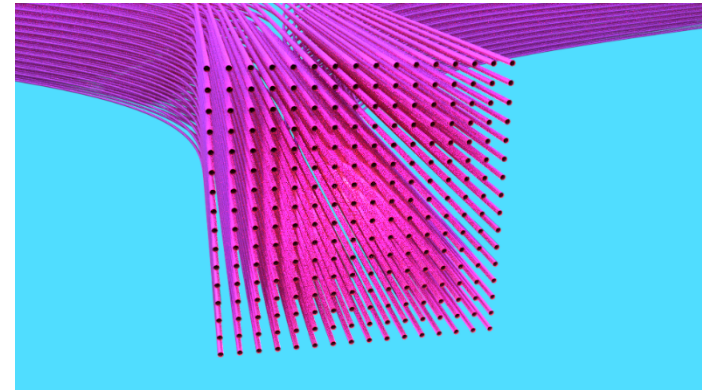


3D waveguides CAD Design

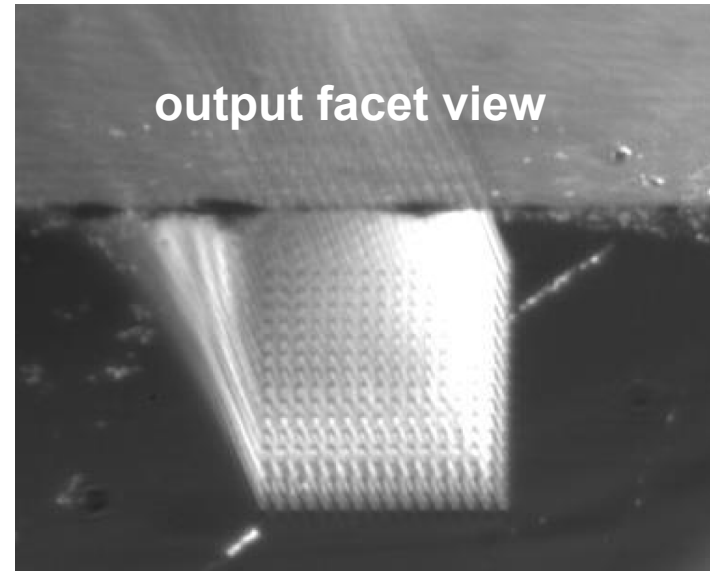
Accuracy at 10 ppb



3D waveguides output pattern



output facet view

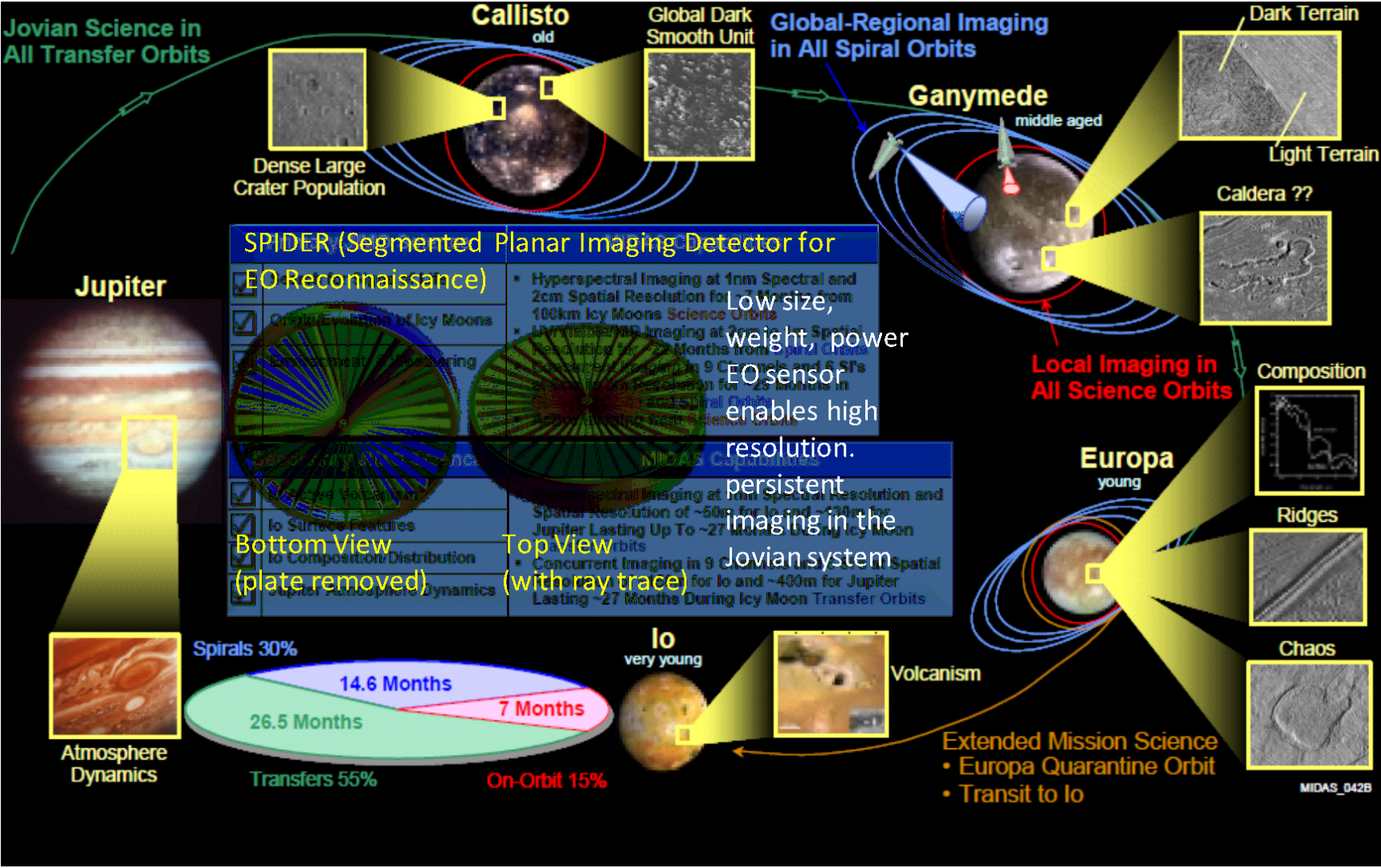




Possible Impacts on SLI-T



Ref: Jupiter Icy Moons Orbiter Reference Mission



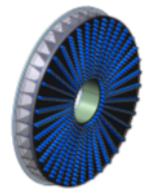


Possible Impacts on SLI-T

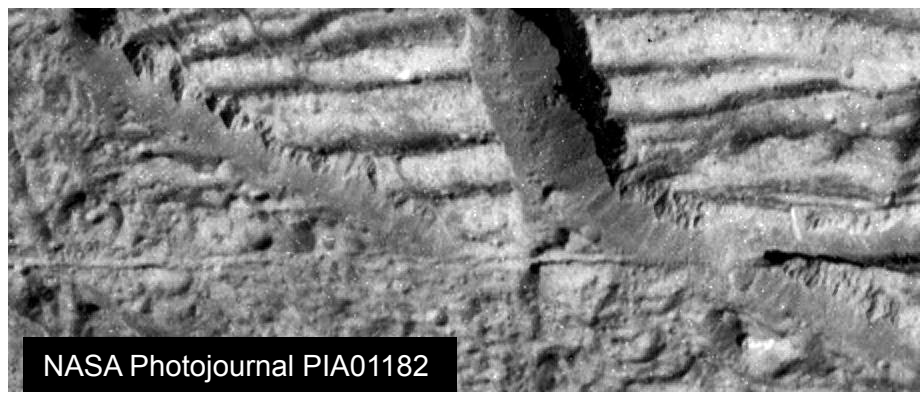
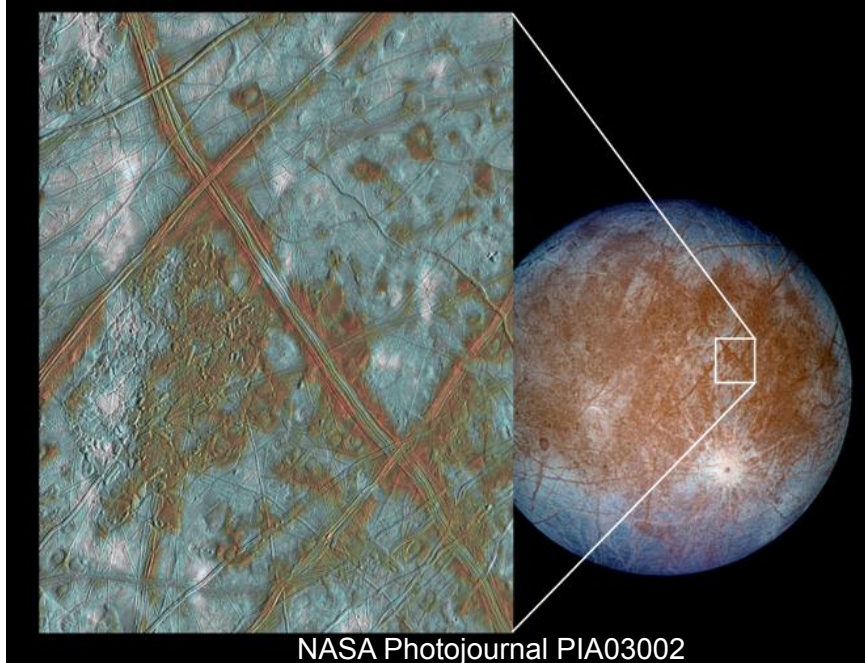
Ref: SPIDER-based Topographical Imager (TI)



- SPIDER Topographical Imager
 - 4 cm diameter aperture (same enclosure)
 - 15 μ rad IFOV \rightarrow 1.5 m Ground-Sampled-Distance (GSD) at 100 km
 - 10 Mpixel area, 150-ms integration time



For the same enclosure, SPIDER could collect 10 \times the area on ground with 17 \times the resolution



Possible Impacts on SLI-T

Ref: Traditional Topographical Imager

Europa Study 2012 Report – Europa Multiple Flyby Mission, JPL D-71990 (2012)

- **Proposed Traditional Imager**
 - **250 μ rad IFOV \rightarrow 25 m Ground-Sampled-Distance (GSD) at 100 km**
 - **4096 detectors, 5.5-ms integration time**
 - **Push-broom mode collection**
 - **5×5×4-cm radiation shielded enclosure (1.3 cm diameter lens)**
 - **2.5 kg unshielded mass**

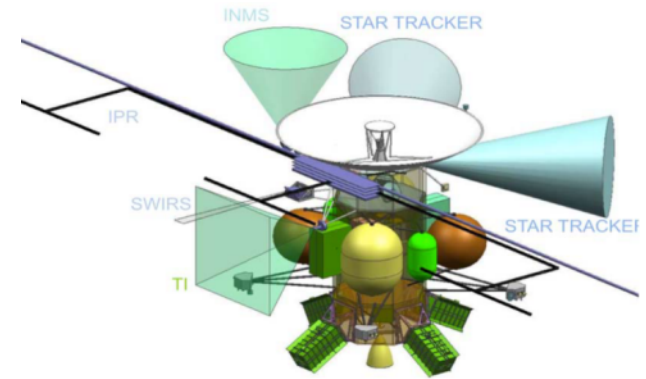
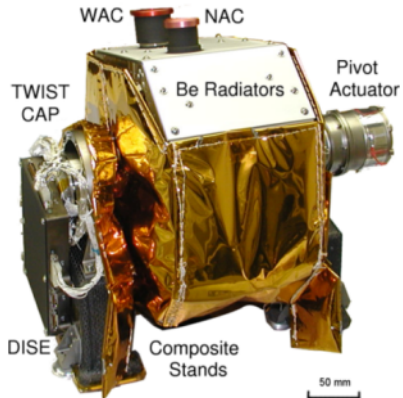
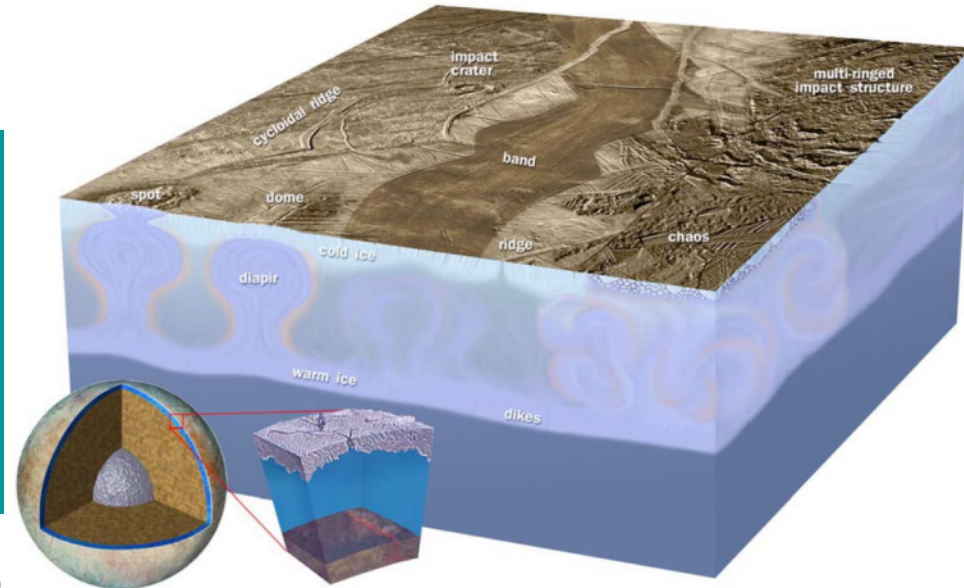
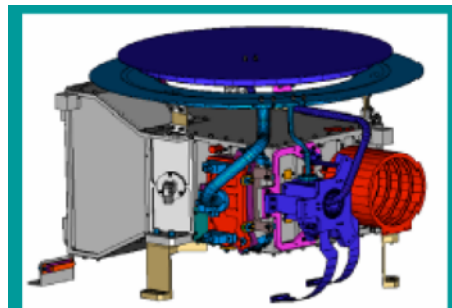


Figure C.2.2-1. Notional model payload accommodation and fields of view.

Diagram of Europa's ice shell

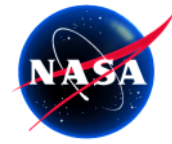


MRO Mars Color Imager (MARCI)



Ralph visible & IR imager, CBE mass 10.67 kg, power 5.3 W

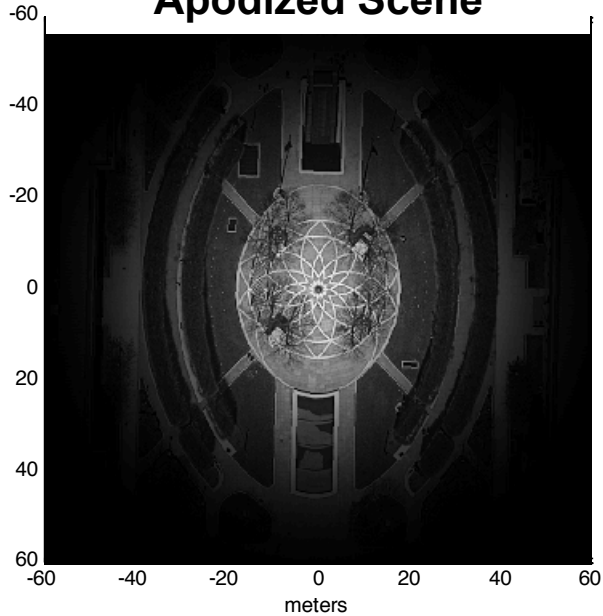
New Horizons Multi-spectral Visible Imaging Camera (MVIC)



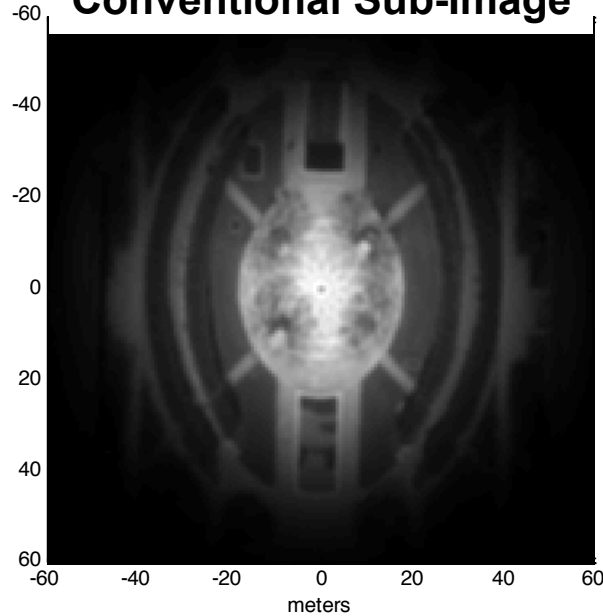
Summary

- A new *Multi-Spectral, Low-Mass, High-Resolution Integrated Photonic Land Imaging Technology*
- ~100x savings in size, weight, (and power) compared to traditional imagers with comparable spatial & spectral resolutions.
- Integrated Chip scale construction on silicon wafers (foundry fabrication capable)
- Integrated spectrally-resolved spatial imaging
- Proof-of-Principle Demonstration of Spectrally Resolved Interferometric Data
- Successful Image Reconstruction Simulations.
- Possible Extensions to SWIR, MWIR, and LWIR
- NIAC Europa preliminary studies indicate exciting possibilities for Landsat.

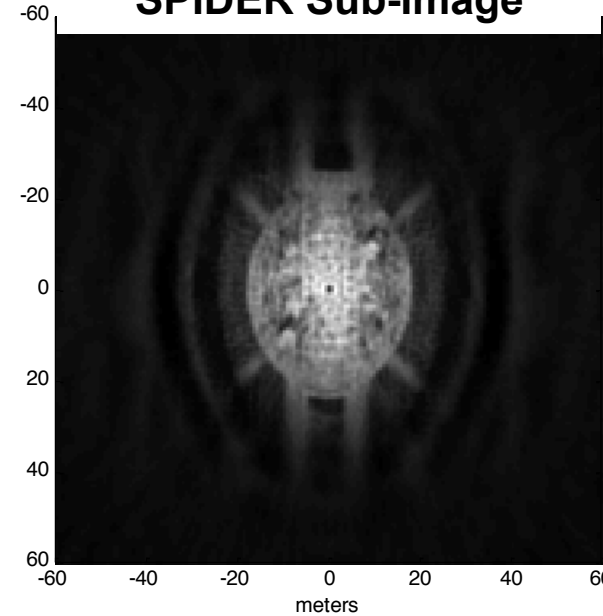
Apodized Scene



Conventional Sub-Image



SPIDER Sub-Image



***No Wiener filter applied**

SPIDER sub-image shows finer detail, but the point-spread function (PSF) sidelobes give a slightly noisy appearance (there was no measurement noise in the simulation)

*Wiener filter is often used to remove blur in images due to linear motion or unfocussed optics



Multilayer 200nm Si_3N_4 PIC Platform – Fabrication Process



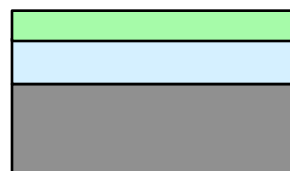
Silicon wafer



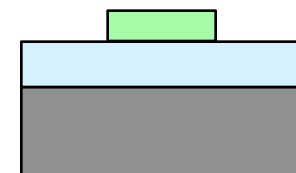
LTO deposition



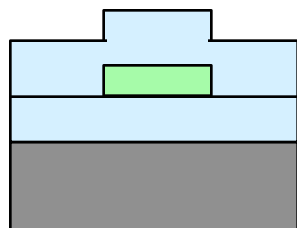
Si_3N_4 deposition



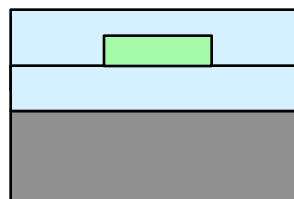
Layer1 pattern



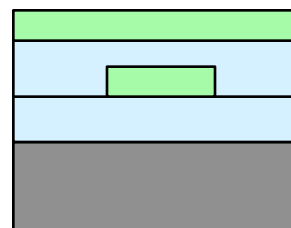
LTO deposition



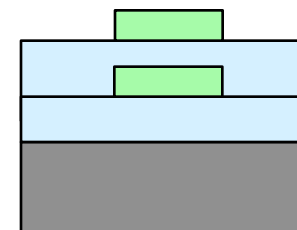
CMP



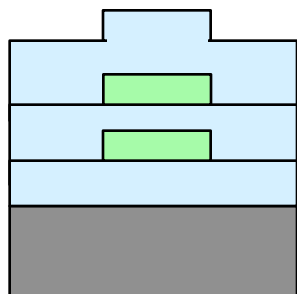
Si_3N_4 deposition



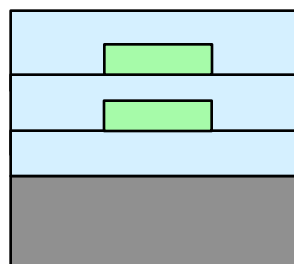
Layer2 pattern



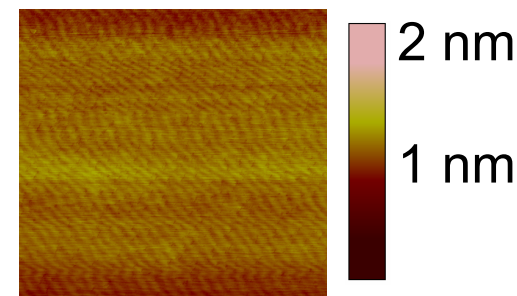
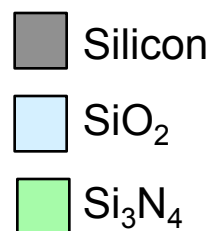
LTO deposition



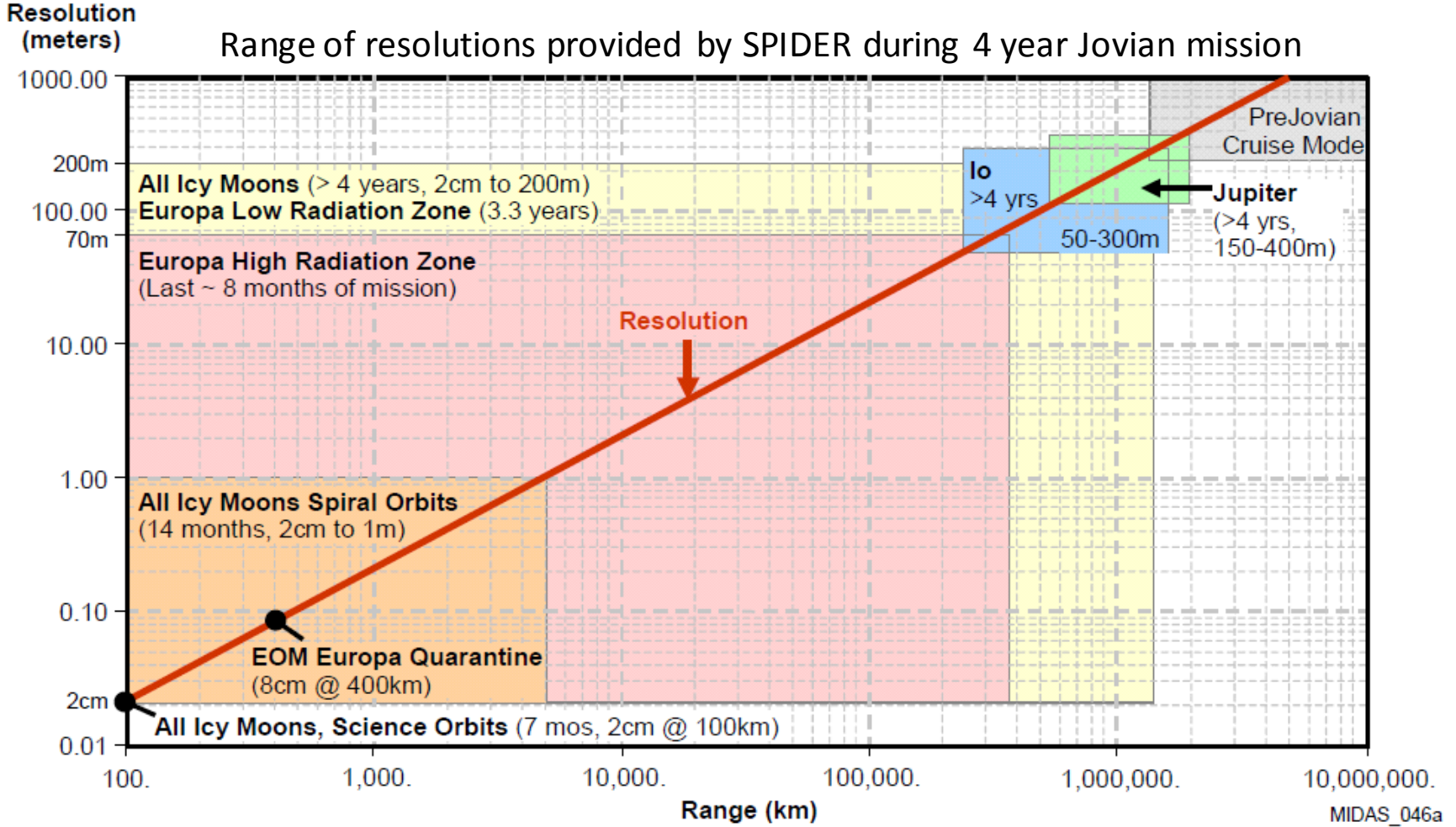
CMP



AFM measurement



1.5 m diameter aperture SPIDER





Europa Flyby Orbit

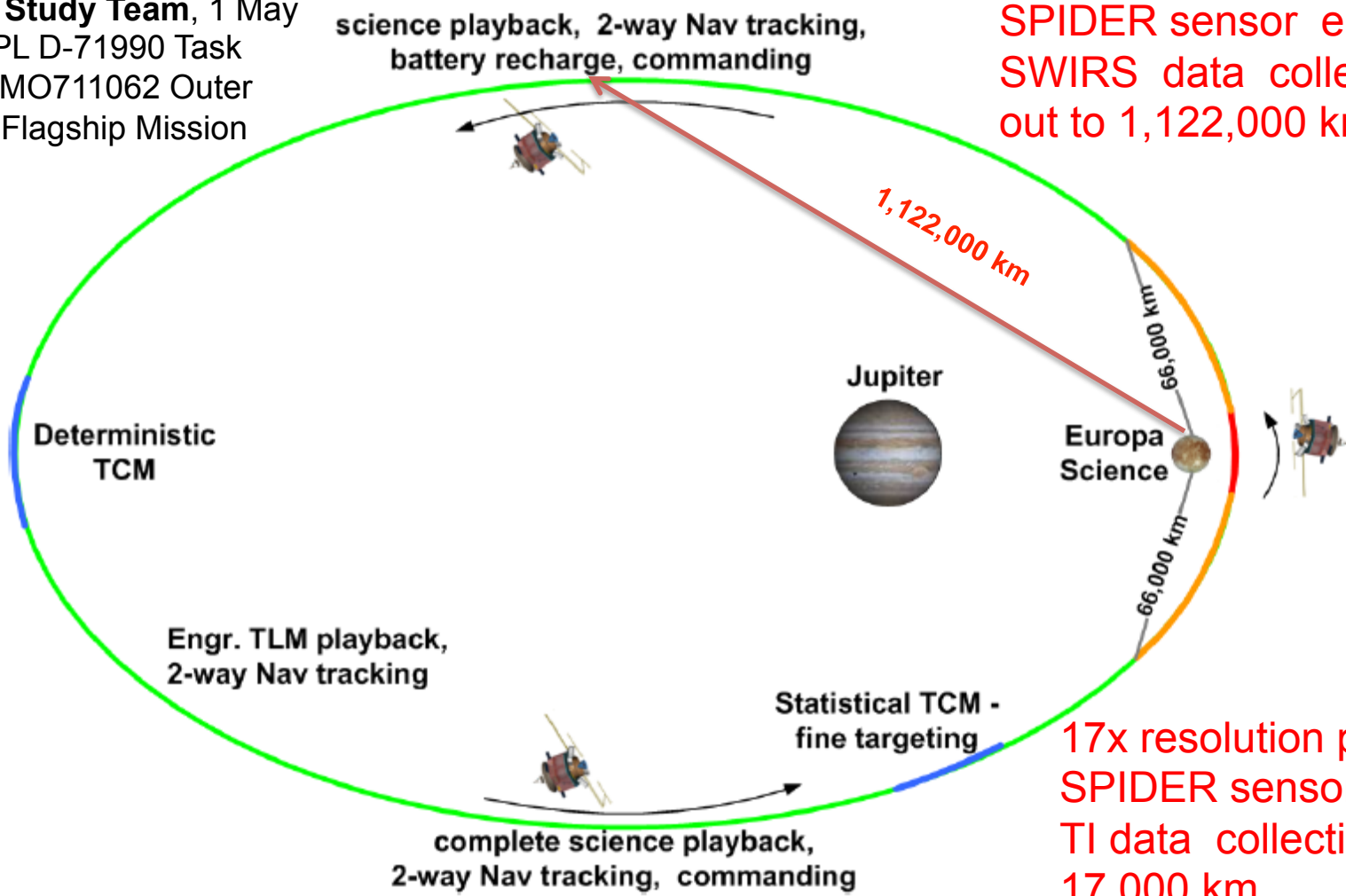


EUROPA STUDY 2012 REPORT

EUROPA MULTIPLE-FLYBY MISSION

Europa Study Team, 1 May 2012, JPL D-71990 Task Order NMO711062 Outer Planets Flagship Mission

17x resolution provided by SPIDER sensor enables SWIRS data collection out to 1,122,000 km



17x resolution provided by SPIDER sensor enables TI data collection out to 17,000 km



Current Prediction for TI Coverage



SPIDER increases both the length (17X) and width (5X) of each swath

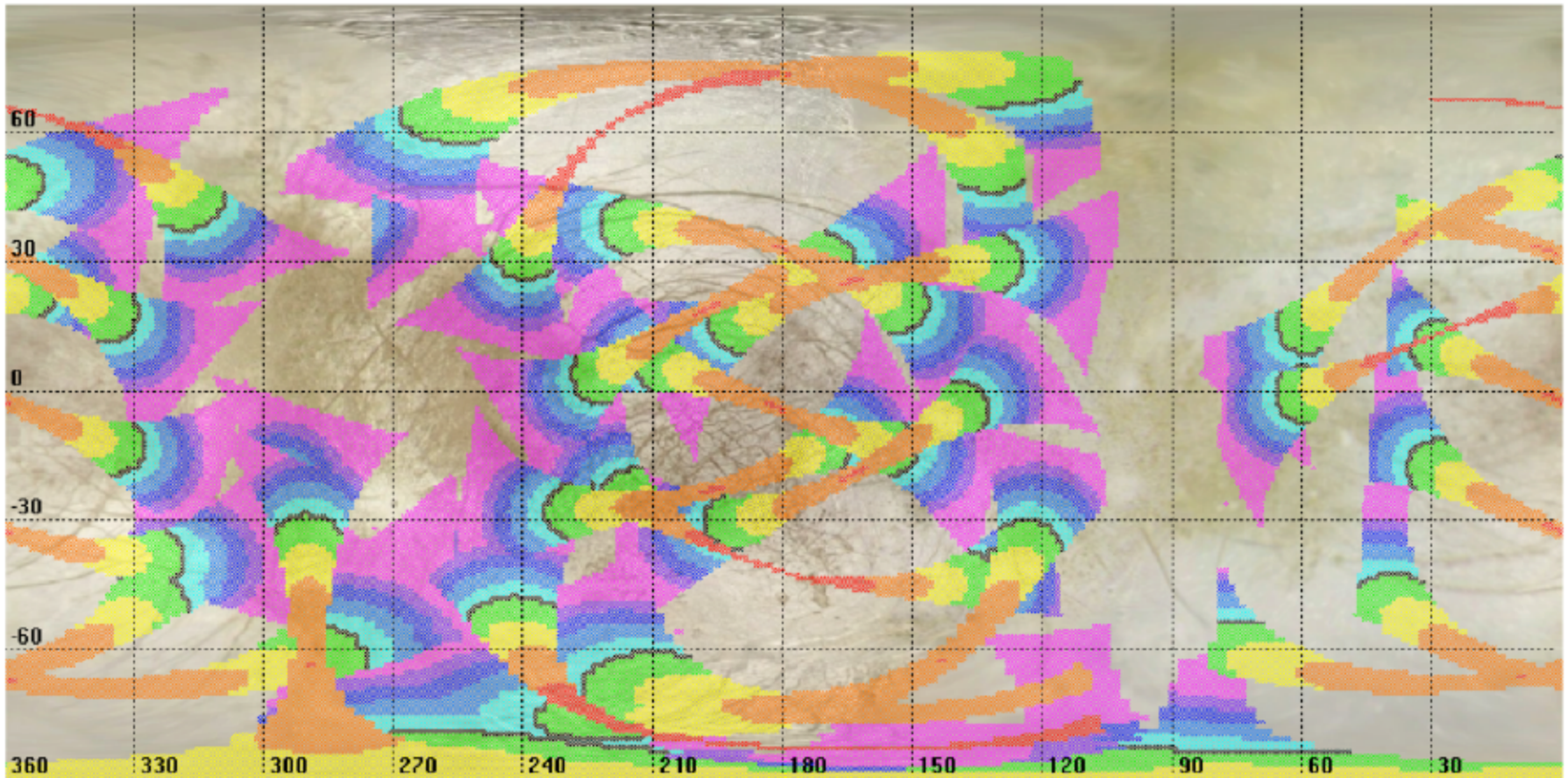


Figure C.2.5-6. TI instrument coverage.

Europa Study Team, 1 May 2012, JPL D-71990 Task Order NMO711062 Outer Planets Flagship Mission



SPIDER increase both the length (17X) and width (5X) of each swath

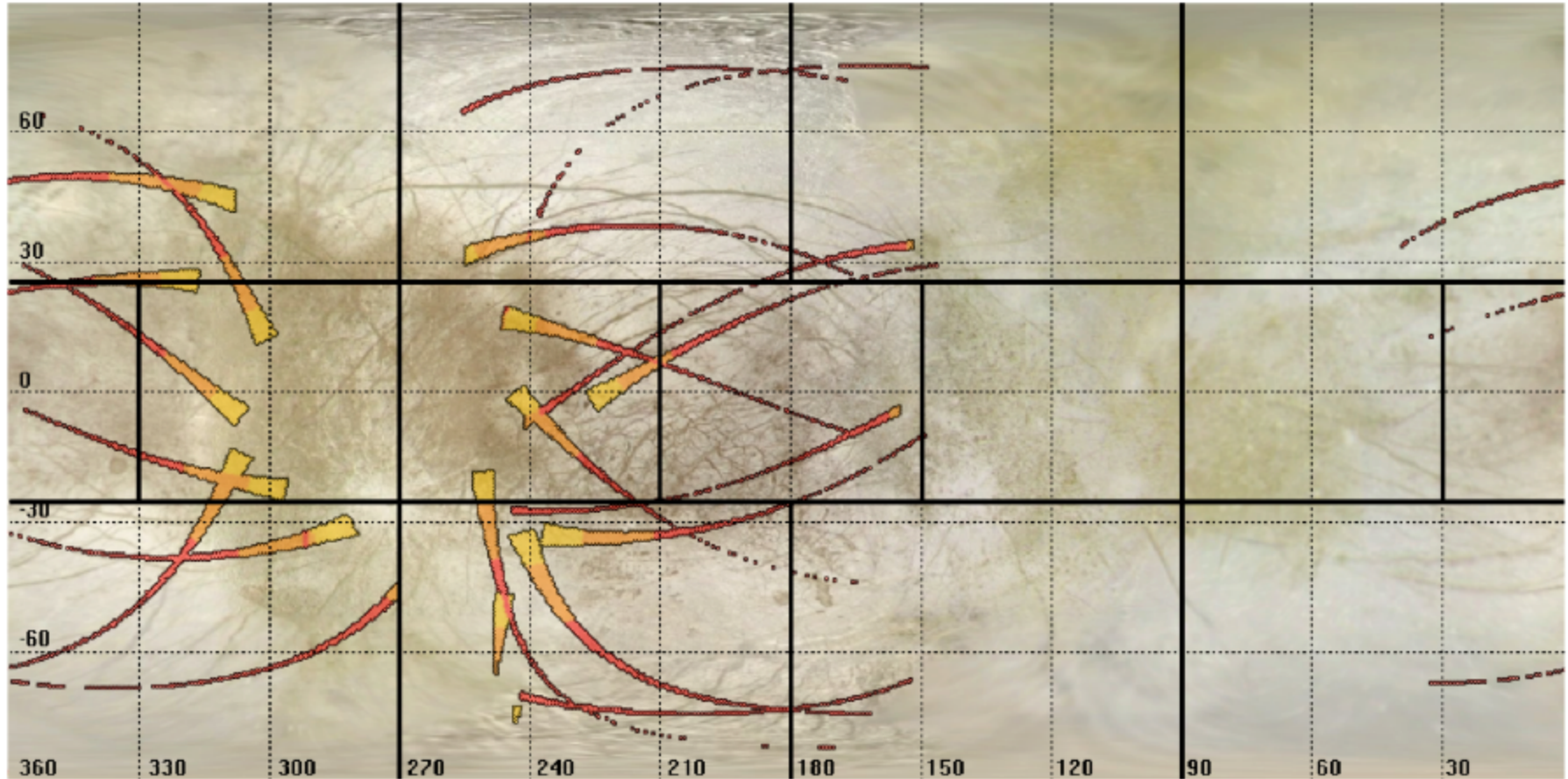
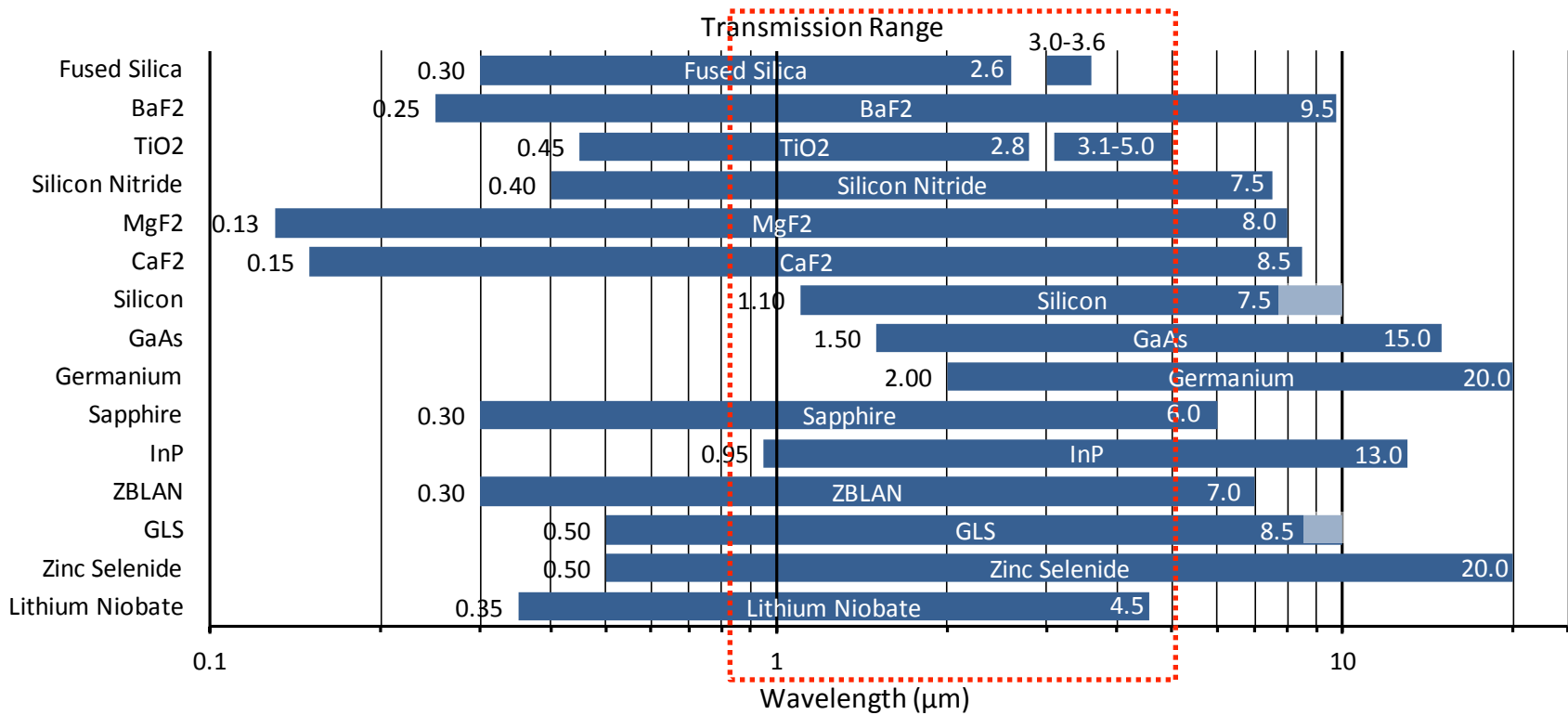


Figure C.2.5-4. SWIRS high-resolution coverage (under 2,000 km altitude).
Europa Study Team, 1 May 2012, JPL D-71990 Task Order
NMO711062 Outer Planets Flagship Mission



Transmission Range of Selected Materials DARPA



Demonstrated Silicon/Silicon Nitride waveguides and InP/InGaAsP waveguides at 4.6 micron in Phase I